



Ethernet Over Ethernet

It can be as simple as that

*Rafie Grinvald
HW & FPGA Manager*

Agenda

- *Ethos Networks Architecture*
- *Ethos 240Gbps Platform & Cards*
- *Design Flow using Concept*
- *Layout and Routing with Allegro Tools*
- *FPGAs Incisive Enterprise Verification*

VoD

IPTV

Mobile Backhauling

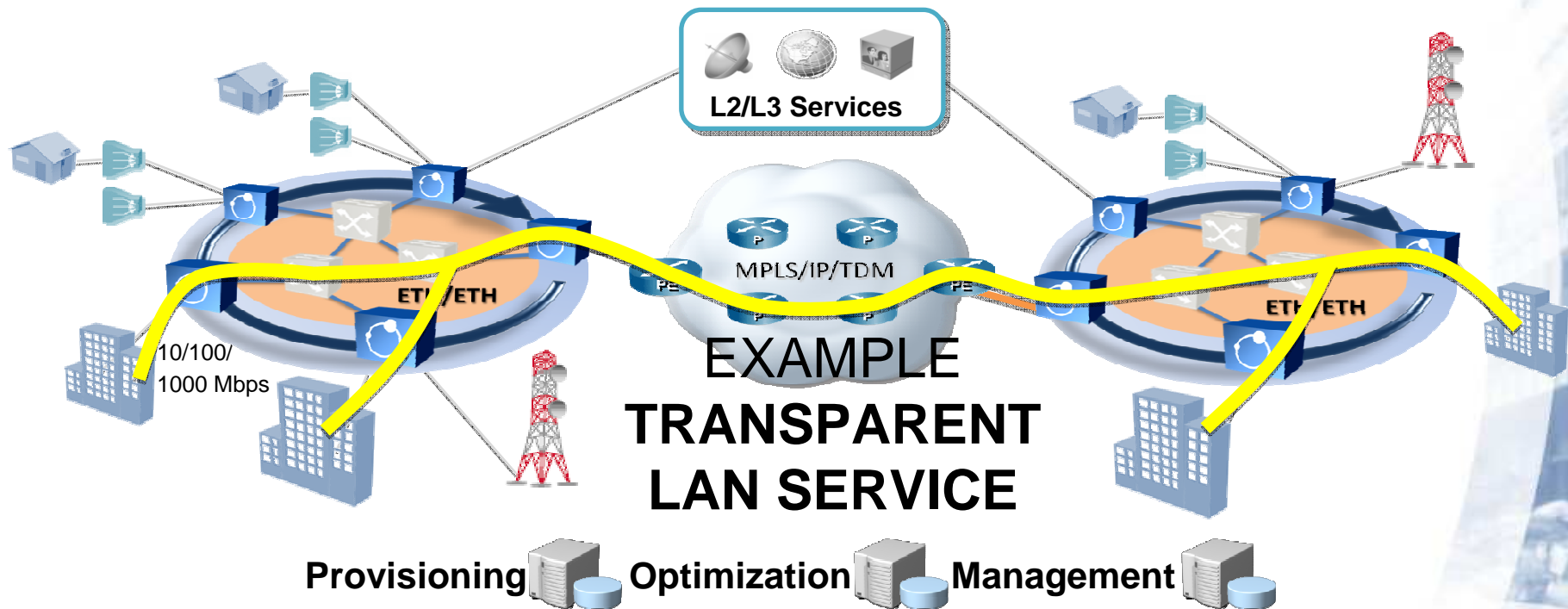
One network

Hundreds of SLAs

Ethos Architecture



System View



How does it work? *Dynamic TE*



DynTE™

1. Traffic admission is controlled at network edge...

2. ... in real-time, based on traffic conditions across the network

3. Every edge holds an updated topology

4. Every edge holds per-flow service profiles

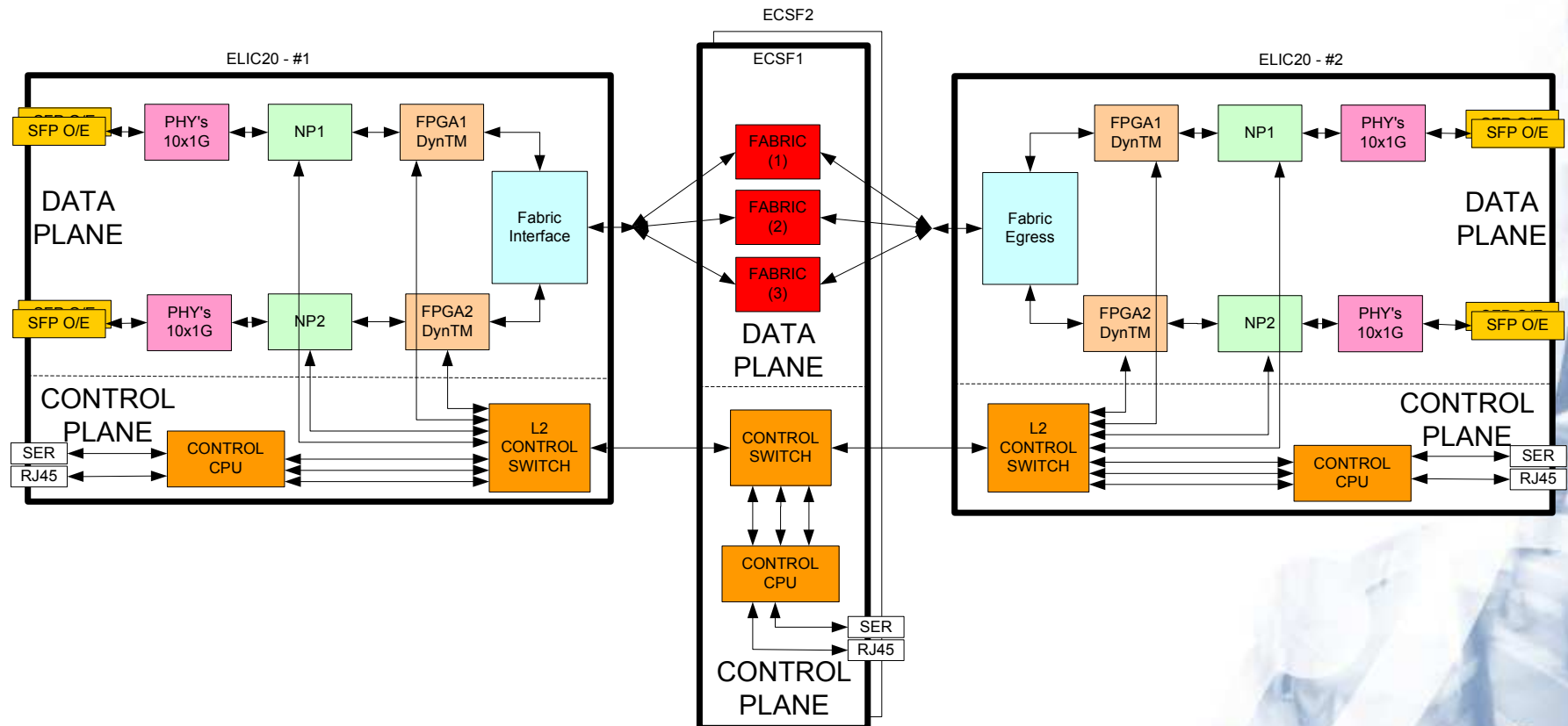
5. Edges communicate transmission intentions to each other every x ms...

6. ..and perform concerted Admissions Control to ensure that SLAs are met

Ethos Solution

- ✓ ***Comprehensive Transport Solution***
- ✓ ***Connection-Oriented Ethernet , PBT***
- ✓ ***QoS guarantees per millions of flows***
- ✓ ***Ethernet efficiency, TDM reliability***
- ✓ ***Network capacity tripled***

System Architecture



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Ethos Platform



Ethos Platforms



Ethos E-20

- 1-2 service slots
- 1-2 x 20 Gbps slots
- High-density GE and 10GE
- AC/DC power



Ethos E-60

- 60 Gbps switching
- 3 x 20 Gbps slots
- High-density GE and 10GE
- AC/DC power



Ethos E-240

- 280 Gbps switching
- 12 x 20 Gbps slots
- High-density GE and 10GE
- 2 systems per rack

Chassis Architecture

Fan Tray &
Thermal Protection

Advanced TCA®

Non-Blocking
All-Ethernet
Architecture

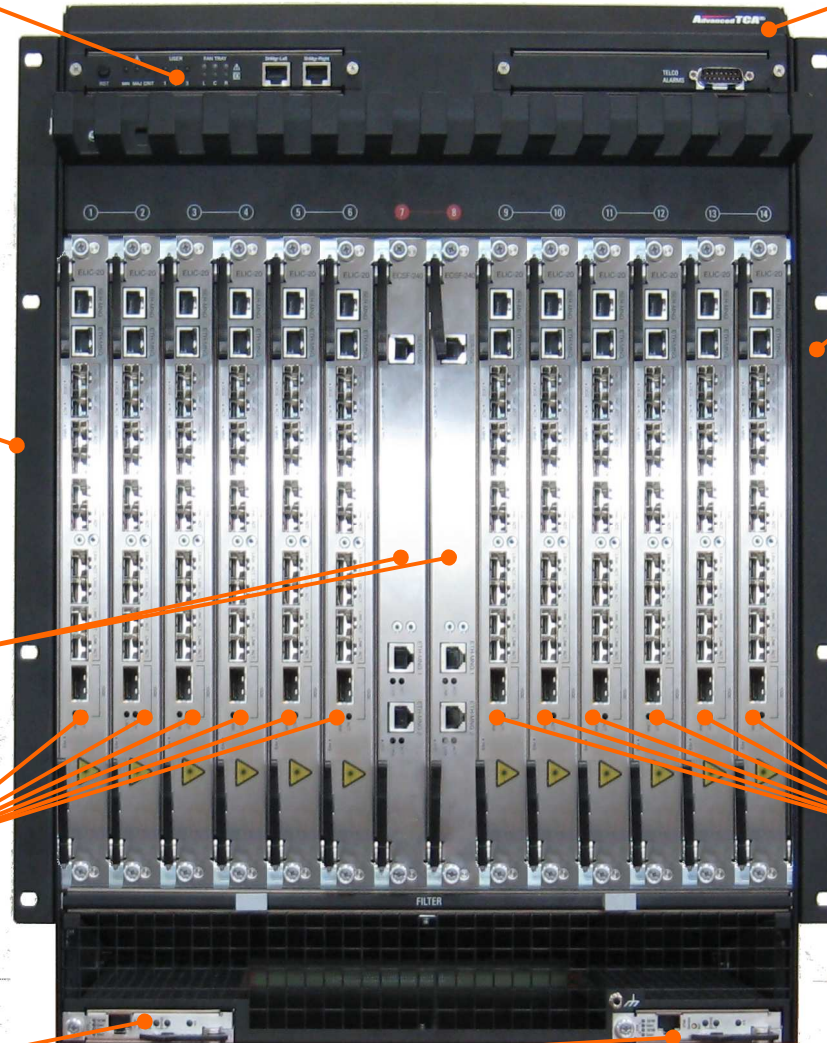
240Gbps backplane

Central Switch Fabric
(ECSF) 1..2

Ethos Line Interface
Cards (ELIC) 1..6

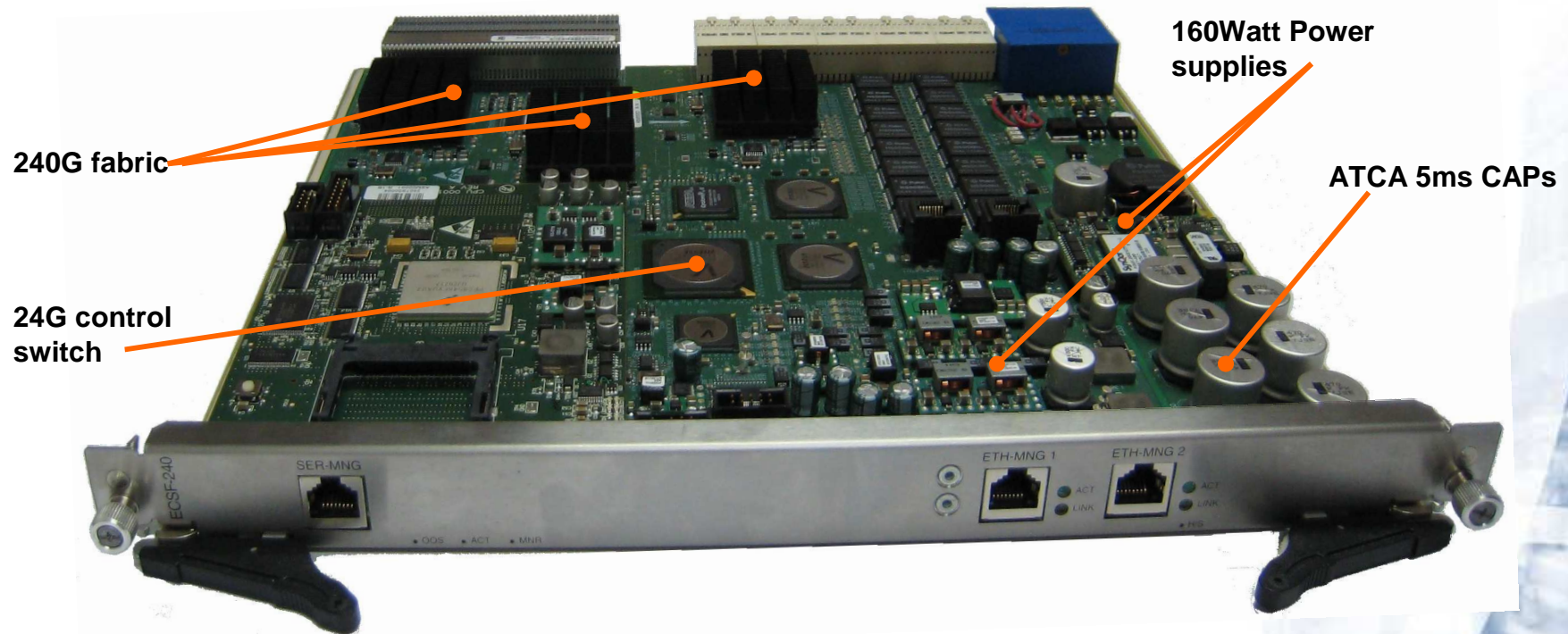
Ethos Line Interface
Cards (ELIC) 7..12

Shelf managers



Ethos
NETWORKS

ECSF 240G

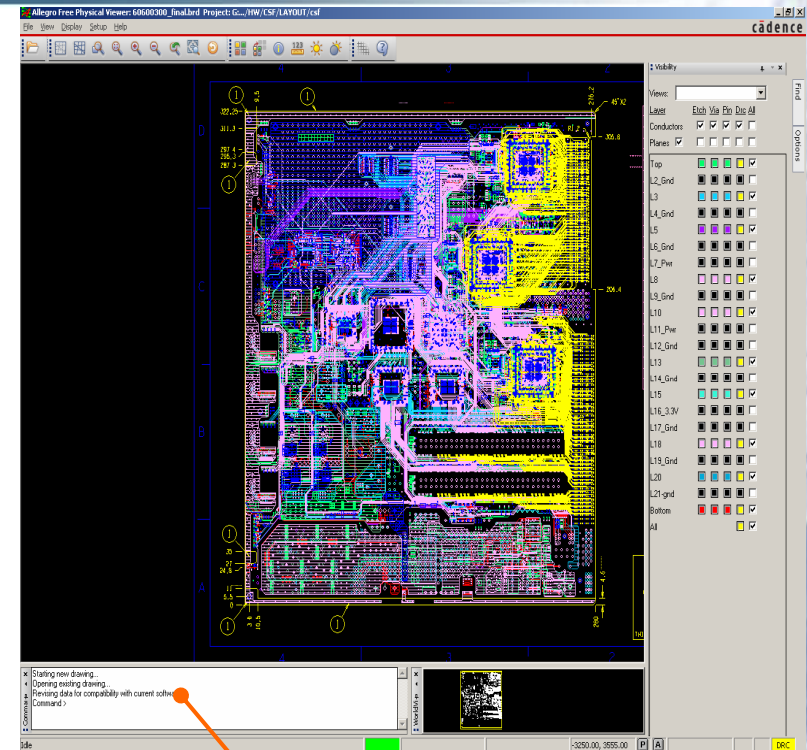


ECSF 240G Features

- *Switch fabric with 240Gbps capacity*
- *Base fabric 24Gpbs control switch (for Ethos management)*
- *160Watt power dissipation*
- *Ethos front panel management*
- *Centralized CPU unit*
- *Serial interfaces from front panel for debug and control*
- *Support ATCA Shelf Manager*
- *Complies to ATCA PICMG3.0*

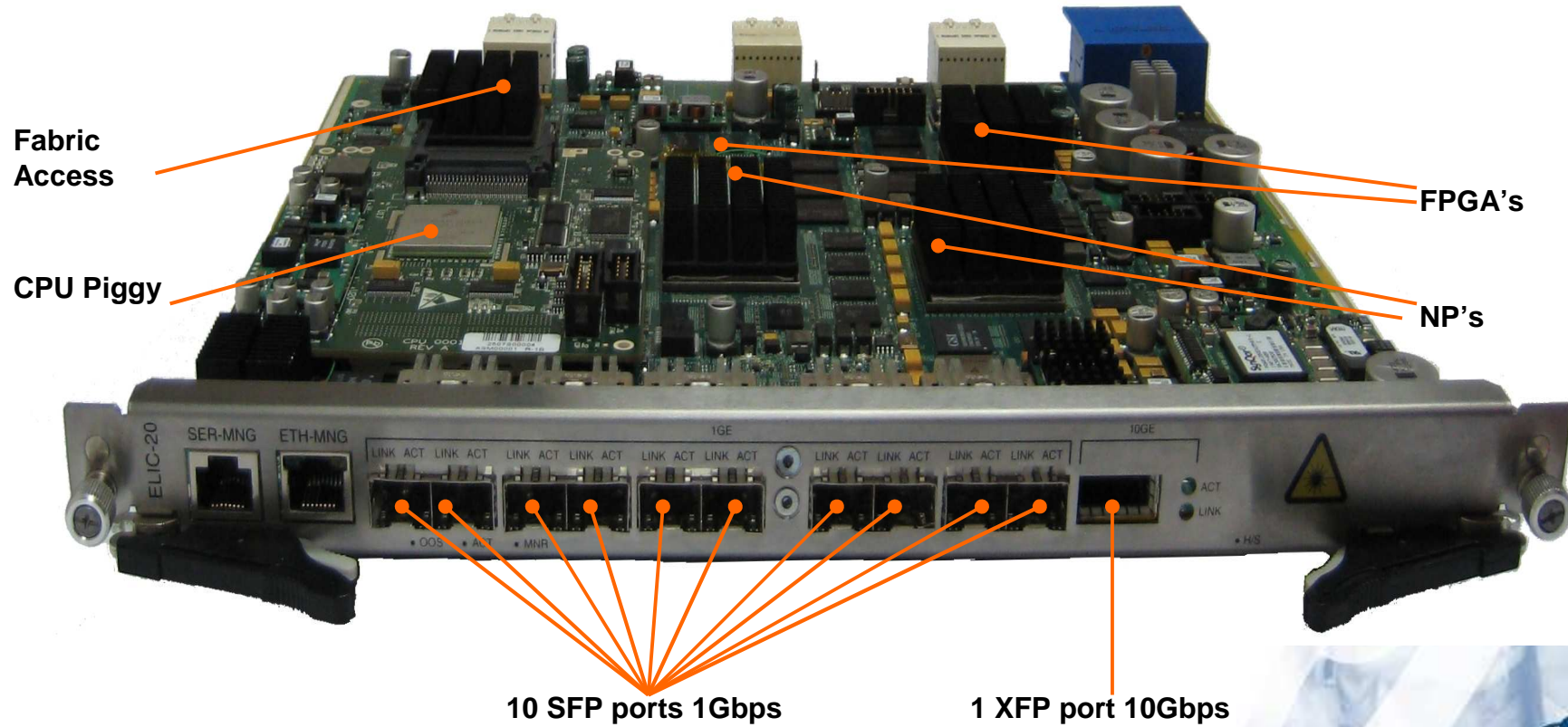
ESCF240G Electrical Features

- 160 Watt per Line Card
- 280mm x 300mm ATCA card
- 22 Layers of PCB, Merix USA
- PCB thickness of 3.1mm
- ~10,000 Via's
- ~3,000 components
- 3 FBGA's with more than 1300 ball grid pins
- 80% of card is high speed differential signals
- 20% of card is high speed single ended signals
- 288 pairs of serial links at 3.125Gbps



Allegro 16.0 Free
Physical Viewer

ELIC 20

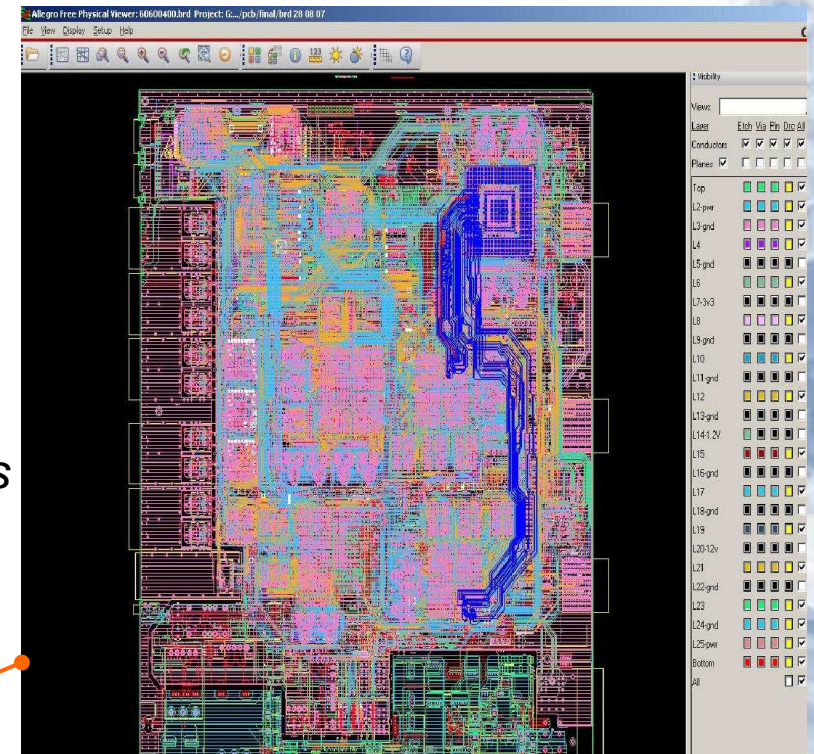


ELIC20 Features

- *20Gbps line card with inline Network Processors*
- *10 x 1Gb SFP copper (1000Base-T) or fiber interfaces*
- *1 x 10Gb XFP fiber interface*
- *20Gb fabric interface*
- *10/100/1000Base-T in front panel for OOB (Out Of Band) management (standalone)*
- *Serial interface from front panel*
- *Complies to ATCA PICMG3.0*
- *Ethos IP fully aware*

ELIC20 Electrical Features

- 200 Watt per line card
- 280mm x 300mm ATCA card
- 26 Layers of PCB with cutting edge laser technology ,Merix USA
- PCB thickness of 3.2mm
- ~49,000 Via's
- ~7,000 components
- 48Gbit DDR2 @ 667Mbps components
- 5 FBGA's with more than 1300 ball grid pins
- 20% of card is high speed differential signals
- 80% of card is high speed single ended signals



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Physical Viewer

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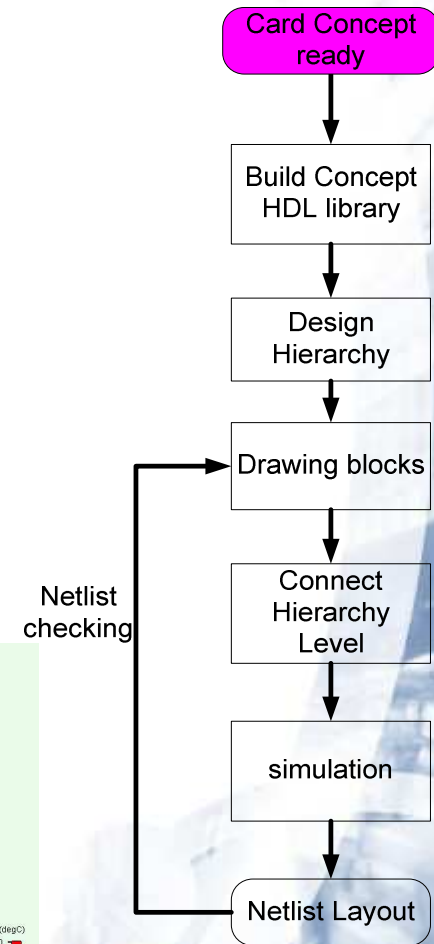
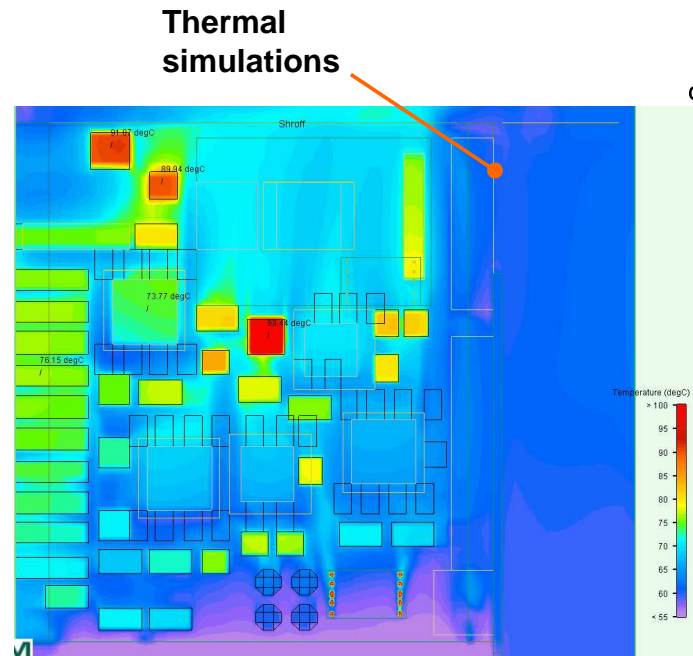
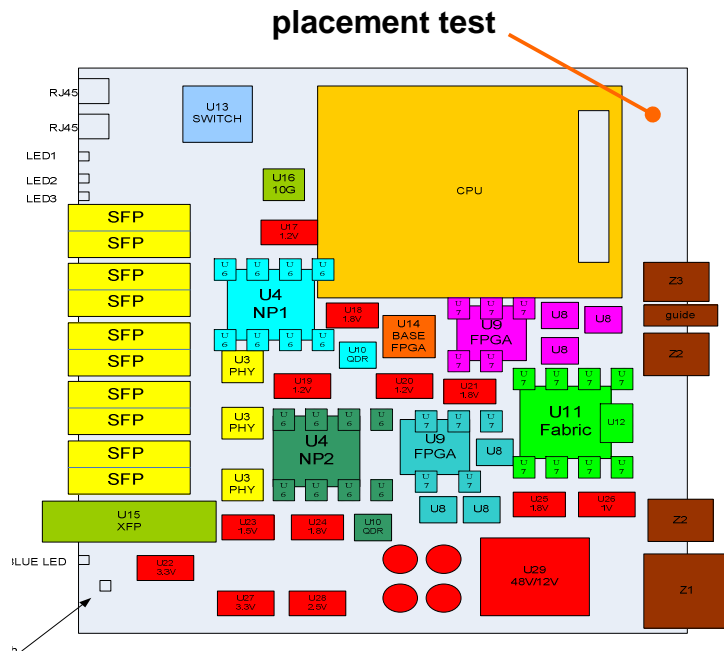
Ethos Design flow with Concept HDL



Design Flow with Concept HDL

Card Architecture:

- *Basic card architecture was ready after 2 months from green light*
- *All major components passed test benches prior to choosing IC vendors*
- *Physical placement tests were done after choosing IC vendors*
- *Physical placement led to thermal simulations tests*



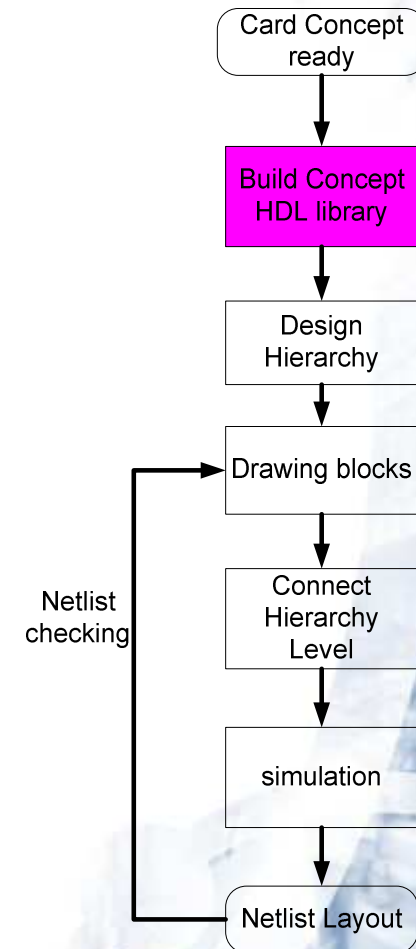
Design Flow with Concept HDL

Concept HDL CAD Library:

- Building around 150 different components
- All components include issues of layout and simulation aspects
- CAD library is in Excel format and can be imported to any operation database

Microsoft Excel - Ethos_catalog.csv

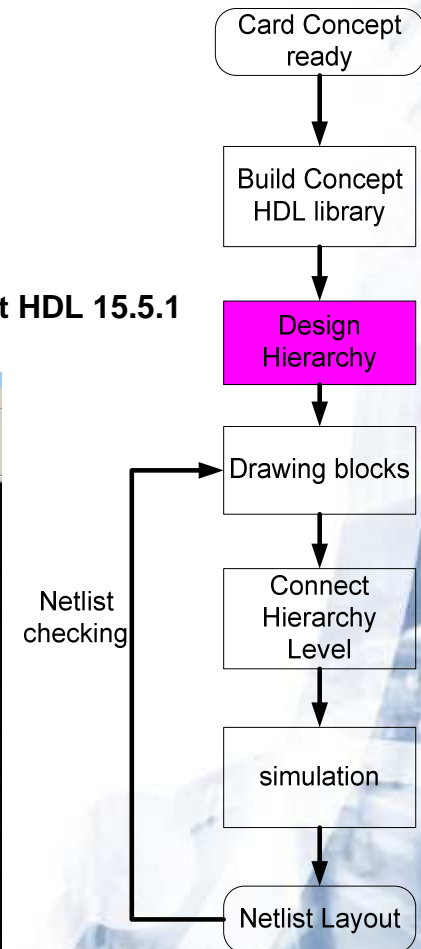
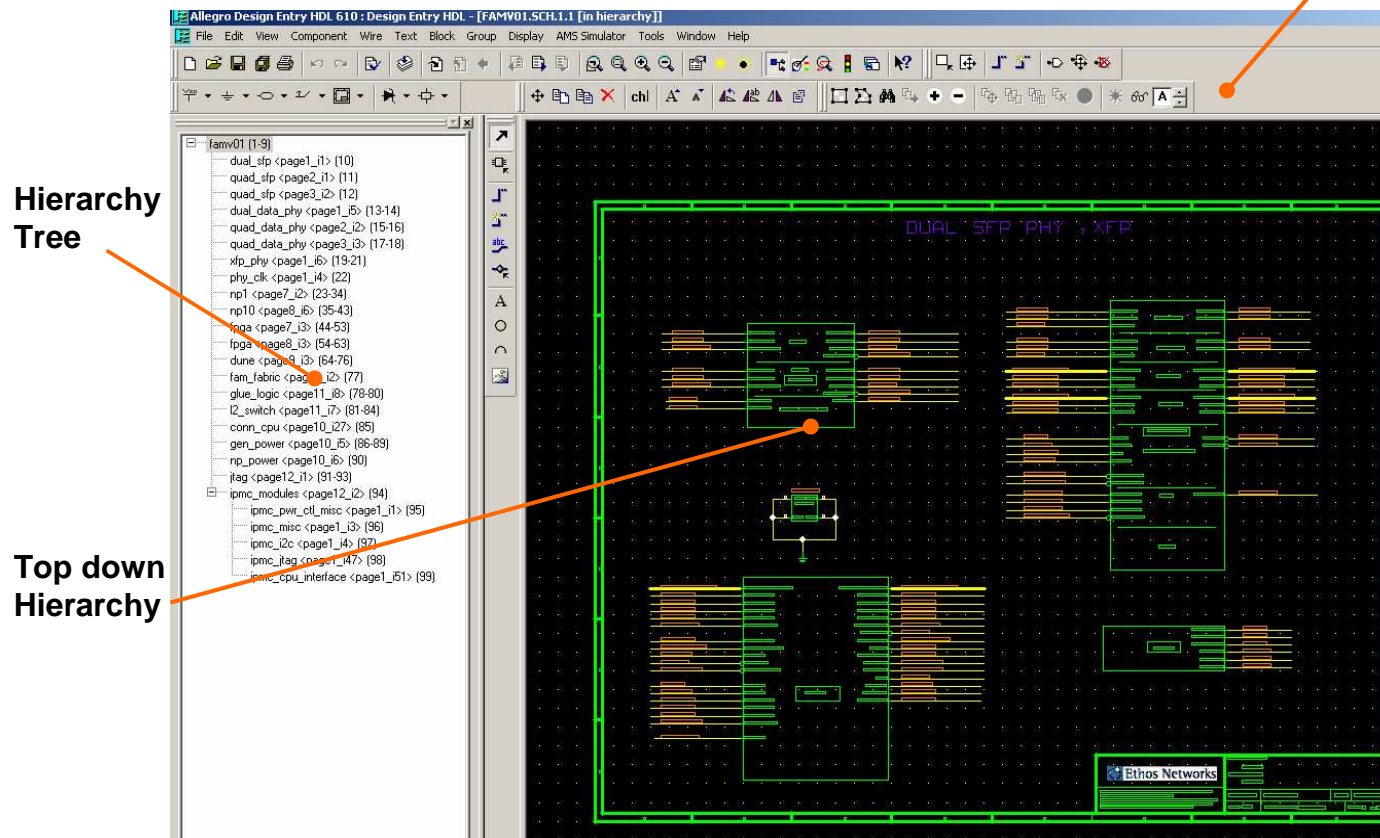
	A	B	C	D	E	F	G	H	I	J	K	L	M	N	O	P	Q	
	Commodit	Subcomm	ETHOS_P	DESCRIP	STATUS	RoHS	VALUE	TOLERAN	JEDEC	TYPACK	TYISYMBOL	MNFR	MNFR	PN	VOLTAGE	CURRENT	POWER	MATERIAL
1	CAP	CAP_NON	CAP00006	CAP_CER	Standard		3.9nF	0.05	603	603	CAP_NON	SAMSUNG	CL10B392	50V				X7R
2	CAP	CAP_NON	CAP00014	CAP_CER	Standard		10nF	0.1	402	402	CAP_NON	MURATA	GRM155R	16V				X7R
4	CAP	CAP_NON	CAP00016	Cap_Cer	Standard		10uF	0.2	1206	1206	CAP_NON	EPCOS	B37875-K	10V				Y5V
5	CAP	CAP_NON	CAP00020	CAP_CER	Standard		100nF	0.1	402	402	CAP_NON	MURATA	GRM155R	10V				X5R
6	CAP	CAP_NON	CAP00023	CAP_CER	Standard	Yes	1nF	0.1	402	402	CAP_NON	MURATA	GRP155R	25V				X7R
7	CAP	CAP_NON	CAP00025	CAP_CER	Standard		2.2uF	0.1	1206	1206	CAP_NON	SAMSUNG	CL31B225	10V				X7R
8	CAP	CAP_NON	CAP00026	CAP_CER	Standard		2.2uF	0.1	603	603	CAP_NON	TAIYO YU	JMK107BJ	6.3V				X7R
9	CAP	CAP_NON	CAP00030	Cap_Cer	Standard		100pF	0.05	603	603	CAP_NON	Kemet	C0603C10	50V				NPO
10	CAP	CAP_NON	CAP00032	CAP_CER	Standard		10uF	0.1	1206	1206	CAP_NON	AVX	1206D106	3V				X5R
11	CAP	CAP_NON	CAP00035	CAP_CER	Standard		0.1uF	0.2	CAP_TH_1	CAP_TH_1	CAP_NON	EVQX	RIF	PHE840M	2.2KV			X2
12	CAP	CAP_NON	CAP00036	Cap_Cer	Standard		100nF	0.1	805	805	CAP_NON	Kemet	C0805C10	50V				X7R
13	CAP	CAP_NON	CAP00054	CAP_CER	Standard		1uF	0.1	603	603	CAP_NON	AVX	0603D106	3V				X5R
14	CAP	CAP_NON	CAP00057	CAP_CER	Standard		47uF	0.2	C1210_H1	C1210_H1	CAP_NON	AVX	12106D476	3V				X5R
15	CAP	CAP_NON	CAP00070	CAP_CER	Standard		4.7pF	0.01	402	402	CAP_NON	AVX	04023A4R	25V				COG
16	CAP	CAP_NON	CAP00072	CAP_CER	Standard	Yes	22pF	0.05	402	402	CAP_NON	AVX	04023C22	25V				X7R
17	CAP	CAP_NON	CAP00078	Cap_Cer	Standard		100nF	0.1	603	603	CAP_NON	Murata	GRM188R	16V				X7R
18	CAP	CAP_NON	CAP00095	CAP_CER	Standard		1nF	0.1	1206	1206	CAP_NON	AVX	1206SC10	1.5KV				X7R
19	CAP	CAP_NON	CAP00104	CAP_CER	Standard		47uF	0.2	1210_2H8	1210_2H8	CAP_NON	AVX	12106D476	3V				X5R
20	CAP	CAP_NON	CAP00105	CAP_CER	Standard		10uF	0.1	1206	1206	CAP_NON	AVX	1206YC10	16V				X7R
21	CAP	CAP_NON	CAP00106	CAP_CER	Standard		0.47uF	0.1	402	402	CAP_NON	AVX	04026D476	3V				X5R
22	CAP	CAP_NON	CAP00107	CAP_CER	Standard	Yes	100nF	0.05	805	805	CAP_NON	AVX	0805C104	100V				
23	CAP	CAP_NON	CAP00108	CAP_CER	Standard	Yes	150nF	0.05	1206	1206	CAP_NON	AVX	1206C15	100V				
24	CAP	CAP_NON	CAP00109	CAP_CER	Standard	Yes	10nF	0.05	603	603	CAP_NON	AVX	0603C10	100V				
25	CAP	CAP_NON	CAP00110	CAP_CER	Standard	Yes	33nF	0.05	805	805	CAP_NON	AVX	0805C33	100V				
26	CAP	CAP_NON	CAP00111	CAP_CER	Standard	Yes	1uF	0.1	C1210_H7	C1210_H7	CAP_NON	Kemet	C1210C10	100V				X7R
27	CAP	CAP_NON	CAP00112	CAP_CER	Standard		2.2nF	0.1	C1812_H5	C1812_H5	CAP_NON	TDK	C4532X7R	2KV				
28	CAP	CAP_NON	CAP00113	CAP_CER	Standard	Yes	2.2uF	0.1	C1812_H1	C1812_H1	CAP_NON	AVX	18121C22	100V				X7R
29	CAP	CAP_NON	CAP00114	CAP_CER	Standard		1uF	0.1	805	805	CAP_NON	Kemet	C0805C10	25V				X7R
30	CAP	CAP_NON	CAP00115	CAP_CER	Standard	Yes	47nF	0.1	805	805	CAP_NON	Kemet	C0805C47	200V				X7R
31	CAP	CAP_NON	CAP00116	CAP_CER	Standard		0.22uF	0.1	402	402	CAP_NON	AVX	04026D226	3V				X5R
32	CAP	CAP_NON	CAP00117	CAP_CER	Standard	Yes	2.2uF	0.2	1206	1206	CAP_NON	AVX	1206YC22	16V				X7R
33	CAP	CAP_NON	CAP00118	CAP_CER	Standard	Yes	22uF	0.2	1206	1206	CAP_NON	AVX	1206YD22	16V				X5R
34	CAP	CAP_NON	CAP00119	CAP_CER	Standard		100uF	0.2	C3225_H1	C3225_H1	CAP_NON	TDK	C3225J80	6.3V				X5R
35	CAP	CAP_POL	CAP00204	Cap_Tant	Standard		10uF	0.1	SIZE-A	SIZE-A	CAP_POL	Kemet	T491A106	10V				TANT
36	CAP	CAP_POL	CAP00214	Cap_Tant	Standard		100uF	0.1	SIZE-D	SIZE-D	CAP_POL	AVX	TPSD107H	10V				TANT
37	CAP	CAP_POL	CAP00225	CAP_TANT	Standard	Yes	330uF	0.2	SIZE-D	SIZE-D	CAP_POL	KEMET	T495D337	16.3V				TANT
38	CAP	CAP_POL	CAP00230	CAP_ELEC	Standard		470uF	0.2	ELECTH	ELECTH	CAP_POL	SANYO	16MV470C	16V				ELEC
39	CAP	CAP_POL	CAP00231	CAP_ELEC	Standard		330uF	0.2	CAPTH_3F	CAPTH_3F	CAP_POL	SANYO	10SEP330	10V				ELEC
40	CAP	CAP_POL	CAP00233	CAP_Alum	Standard	Yes	330uF	0.2	SIZE-X	SIZE-X	CAP_POL	KEMET	A700C337	4V				ELEC
41	CAP	CAP_POL	CAP00236	CAP_ELEC	Standard		330uF	0.2	C-C101X1C	C-C101X1C	CAP_POL	Nichicon	PC1H1C331	16V				ELEC
42	CAP	CAP_POL	CAP00237	CAP_ELEC	Standard	Yes	330uF	0.2	ELECSM	ELECSM	CAP_POL	SANYO	10SV330	10V				ELEC
43	CAP	CAP_POL	CAP00238	CAP_ELEC	Standard	Yes	420uF	0.2	ELECSM	ELECSM	CAP_POL	SANYO	16CF470K	16V				ELEC



Design Flow with Concept HDL

Design Hierarchy:

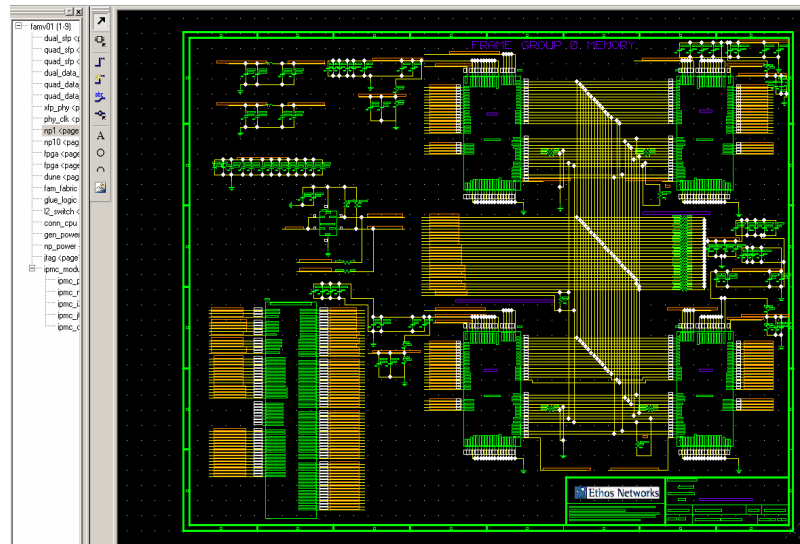
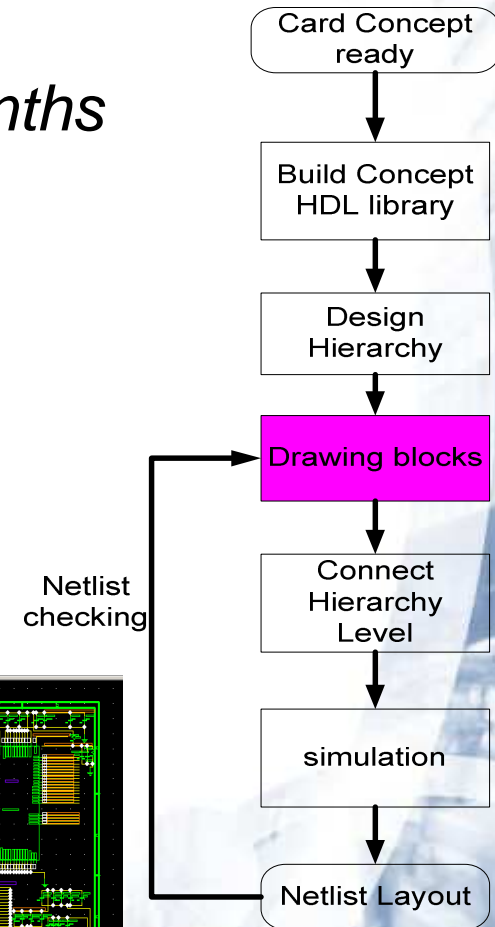
- Top down hierarchy design
- Design comprised of over 100 pages
- Database of 500MB (in HDL format)



Design Flow with Concept HDL

Drawing Blocks:

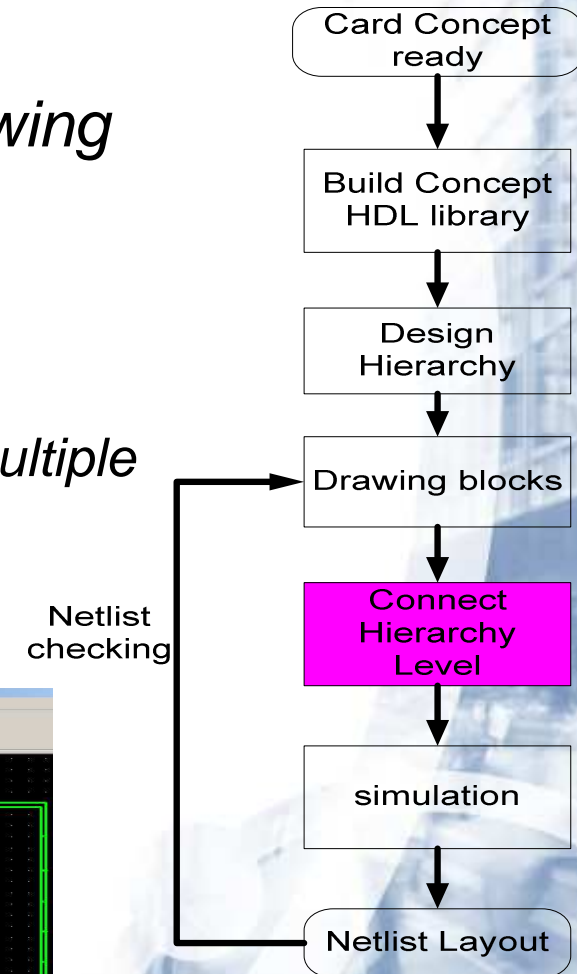
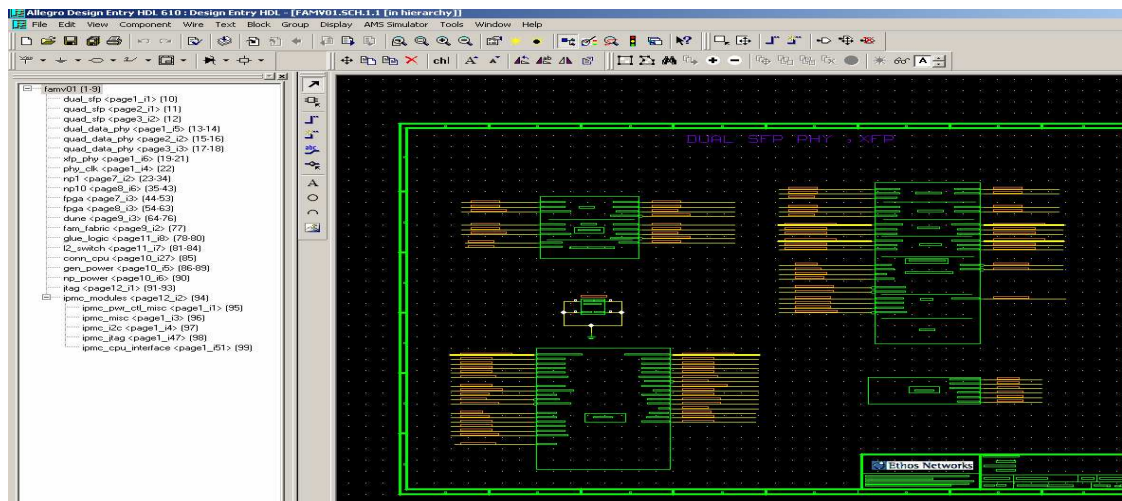
- *Design of ~7,000 components around 3 months*
- *~25,000 nets over the ELIC card drawn*
- *Design with layout consideration:*
 - *Designing power planes*
 - *Adding constraints*
 - *EMC considerations*
 - *Mechanical issues*



Design Flow with Concept HDL

Integration Hierarchy:

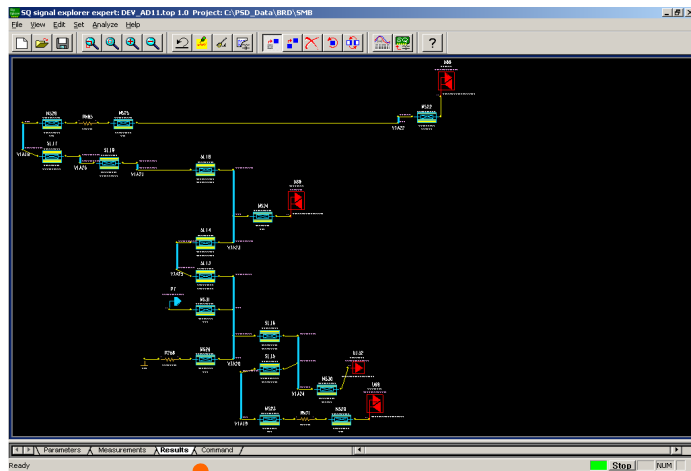
- The use of block instantiations reduced drawing cycle
- BOM (Bill Of Material) issues:
 - All components marked with N/A tag
 - BOM variants tool was implemented (including multiple assemblies)
 - BOM can be easily exported to excel and to any operational data base



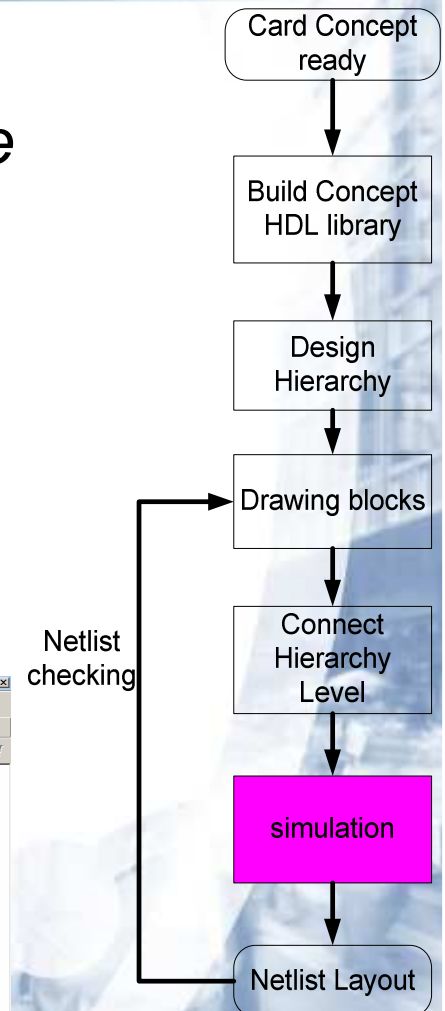
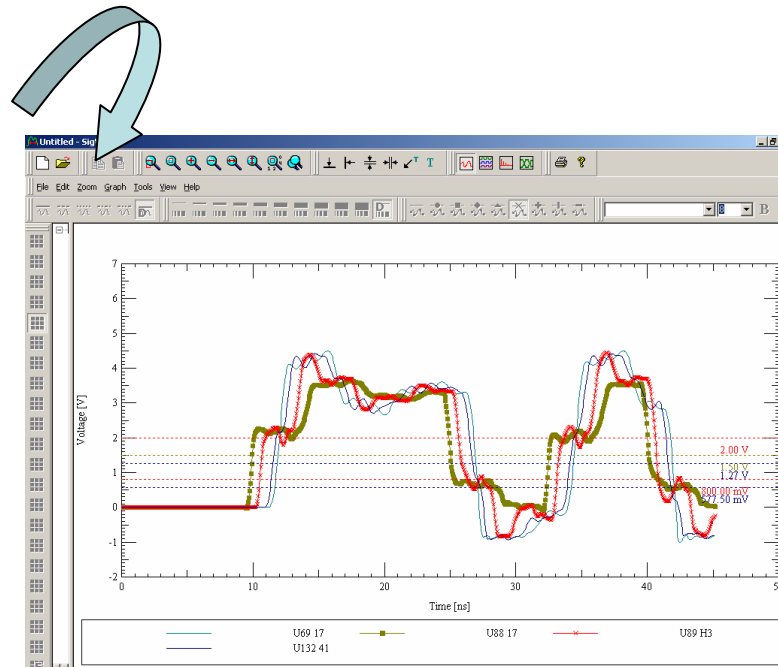
Design Flow with Concept HDL

Simulations:

- Only major items were tested at simulation phase (DDRII, differential lines)
- SigXplorer simulation suite was used
- IBIS up to 1GHz or SPICE models can be used



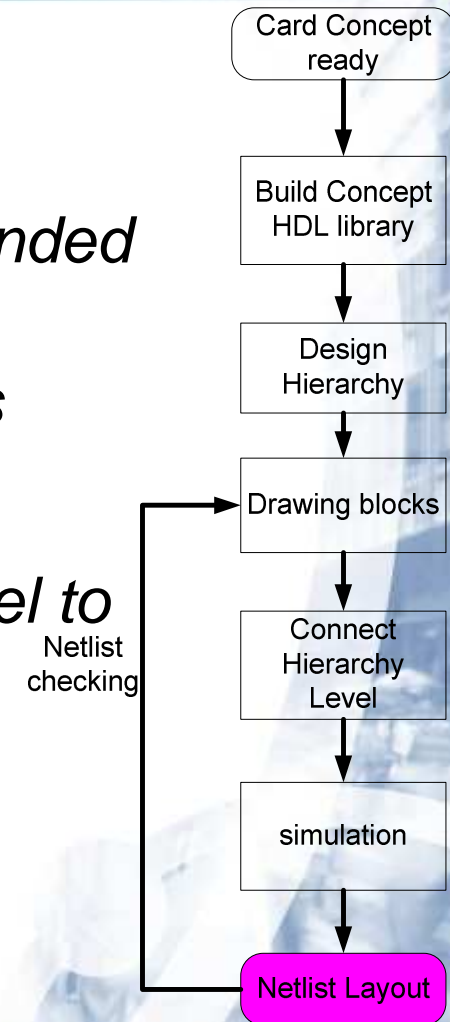
SigXplorer Testing example



Design Flow with Concept HDL

Netlist Checking:

- Only major components were tested
- DRC (Design Rule Check) running is recommended before Netlist checking
- No software application can test logical insights
- Bug fixing is done at drawing blocks phase
- Netlist checking takes around 1 month in parallel to routing (25,000 nets)
- All nets should include routing name



Netlist checking
with proprietary
scripts

```
File Edit Format View Help
A11_DDR_CM1: R1611.1 U99.P7 U19.AD1
A11_DDR_FG0: R441.1 U103.P7 U104.P7 U31.P7 U32.P7 U19.AR27
A11_DDR_FG1: R1752.1 U30.P7 U105.P7 U29.P7 U106.P7 U19.AU12
A11_DDR_SM: R289.1 U91.P7 U94.P7 U14.P7 U17.P7 U19.M4
A11_DDR_SM_2: R598.1 U125.P7 U126.P7 U56.P7 U57.P7 U47.M4
A12_DDR_CM1: R319.1 U21.R2 U19.AH7
A12_DDR_CM1: R1667.1 U99.R2 U19.AD2
A12_DDR_FG0: R1750.1 U103.R2 U104.R2 U31.R2 U32.R2 U19.AT27
A12_DDR_FG1: R1763.1 U30.R2 U105.R2 U29.R2 U106.R2 U19.AT12
A12_DDR_SM: R1338.1 U91.R2 U94.R2 U14.R2 U17.R2 U19.N8
A12_DDR_SM_2: R2720.1 U125.R2 U126.R2 U56.R2 U57.R2 U47.N8
A13_DDR_CM1: R401.1 U21.R8 U19.AK3
A13_DDR_CM1: R1602.1 U99.R8 U19.AB9
A13_DDR_FG0: R442.1 U103.R8 U104.R8 U31.R8 U32.R8 U19.AN27
A13_DDR_FG1: R428.1 U30.R8 U105.R8 U29.R8 U106.R8 U19.AV11
A13_DDR_FG1: R291.1 U91.R8 U94.R8 U14.R8 U17.R8 U19.N7
A13_DDR_SM: R599.1 U125.R8 U126.R8 U56.R8 U57.R8 U47.N7
A14_DDR_CM1: R1325.1 U91.R3 U94.R3 U14.R3 U17.R3 U19.L1
A14_DDR_SM_2: R2721.1 U125.R3 U126.R3 U56.R3 U57.R3 U47.L1
A1_DDR_CM1: R343.1 U21.M3 U19.AL5
A1_DDR_CM1: R1656.1 U99.M3 U19.AF4
A1_DDR_FG0: R438.1 U103.M3 U104.M3 U31.M3 U32.M3 U19.AK29
A1_DDR_FG1: R425.1 U30.M3 U105.M3 U29.M3 U106.M3 U19.AT14
A1_DDR_SM: R261.1 U91.M3 U94.M3 U14.M3 U17.M3 U19.P2
A1_DDR_SM_2: R595.1 U125.M3 U126.M3 U56.M3 U57.M3 U47.P2
A2_DDR_CM1: R371.1 U21.M7 U19.AL4
A2_DDR_CM1: R1597.1 U99.M7 U19.AC10
A2_DDR_FG0: R431.1 U103.M7 U104.M7 U31.M7 U32.M7 U19.AK27
A2_DDR_FG1: R418.1 U30.M7 U105.M7 U29.M7 U106.M7 U19.AV14
A2_DDR_SM: R233.1 U91.M7 U94.M7 U14.M7 U17.M7 U19.T12
A2_DDR_SM_2: R588.1 U125.M7 U126.M7 U56.M7 U57.M7 U47.T12
A2_V1*: U116.5 U116.7
A3_DDR_CM1: R329.1 U21.N2 U19.AM1
A3_DDR_CM1: R1695.1 U99.N2 U19.AE1
A3_DDR_FG0: R1749.1 U103.N2 U104.N2 U31.N2 U32.N2 U19.AL28
A3_DDR_FG1: R1762.1 U30.N2 U105.N2 U29.N2 U106.N2 U19.AW14
A3_DDR_SM: R1353.1 U91.N2 U94.N2 U14.N2 U17.N2 U19.V12
A3_DDR_SM_2: R1719.1 U125.N2 U126.N2 U56.N2 U57.N2 U47.V12
A4_DDR_CM1: R404.1 U21.N8 U19.AM2
A4_DDR_CM1: R1624.1 U99.N8 U19.AE2
A4_DDR_FG0: R450.1 U103.N8 U104.N8 U31.N8 U32.N8 U19.AJ27
```

Concept HDL Summary

Advantages:

- *Works well with large schemes (~500M)*
- *HDL/ASCII engine enables easy reading and block checking*
- *High integration with simulation and layout Software*

Possible Improvements:

- *Support of team work*
- *ConceptHDL unstable under Linux*
- *Limitations on back annotation from Layout tool to ConceptHDL with instantiations*

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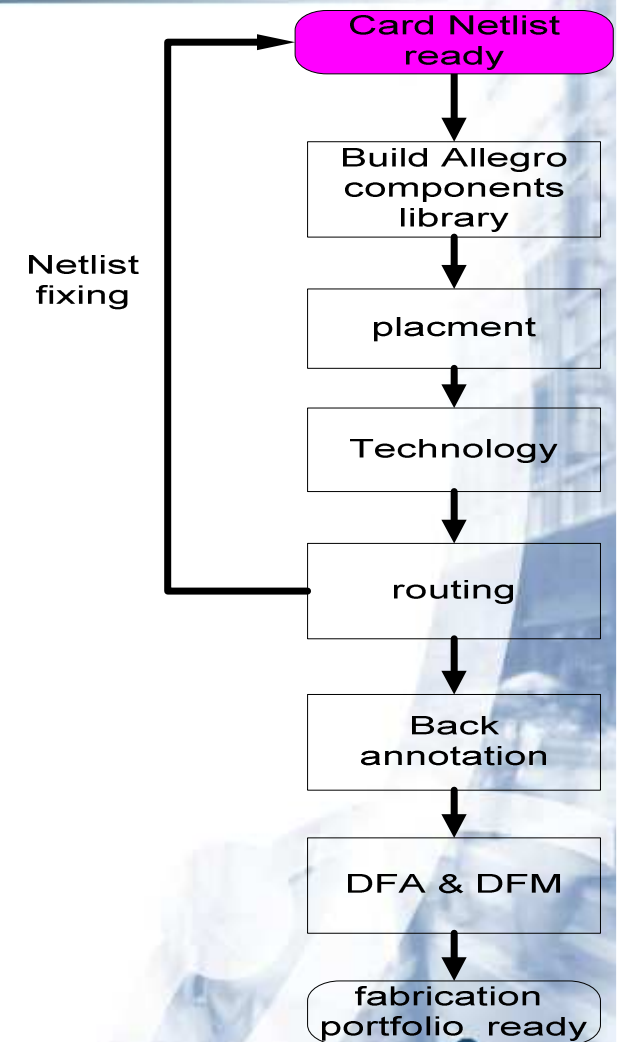
Ethos Card layout with Allegro



Layout Flow with Allegro

Card Netlist Ready:

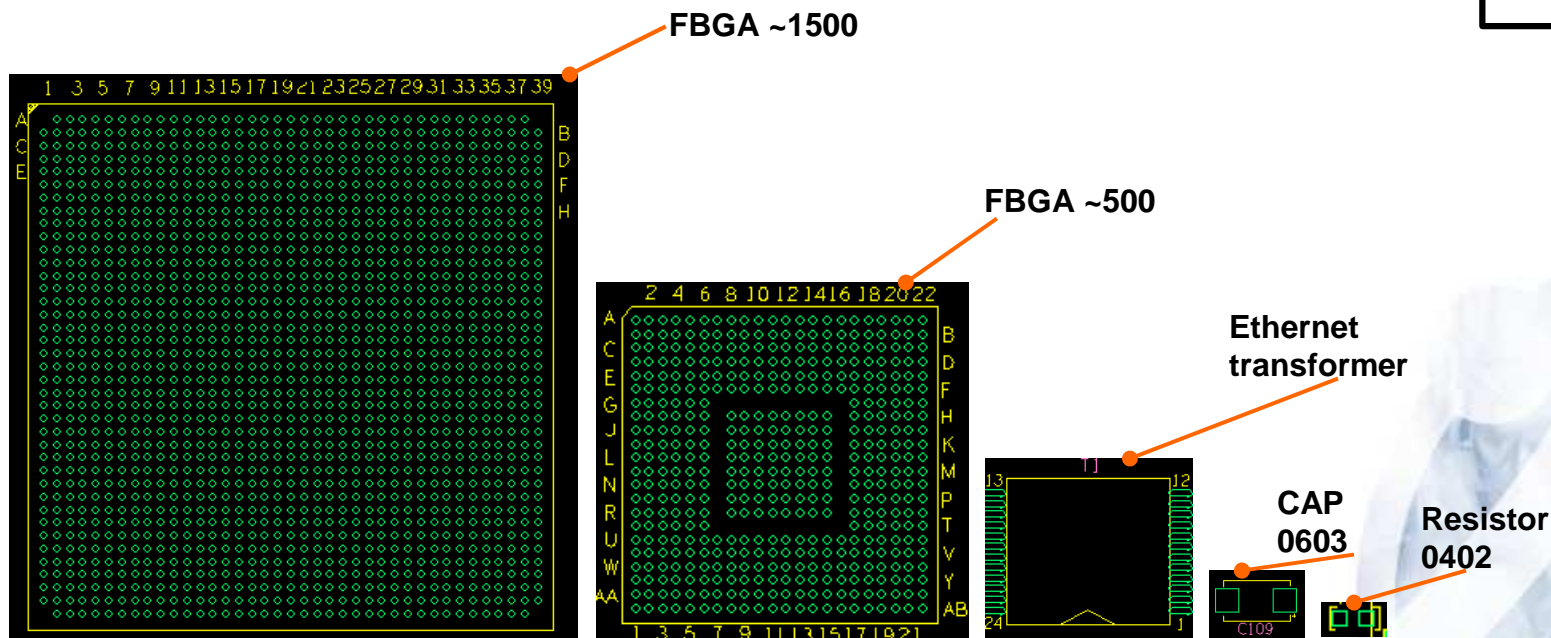
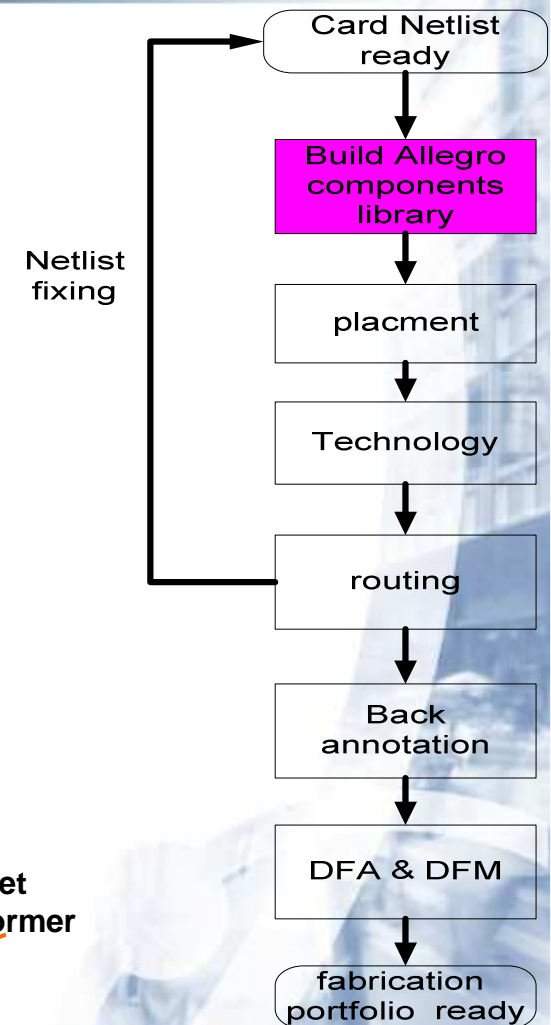
- *Netlist passed with bugs, but with full components count*
- *First Netlist draft passed after 3 months of scheme drawings*
- *Support of technologist engineer begins from netlist to fabrication portfolio*



Layout Flow with Allegro

Components Building:

- All datasheets should be ready before passing netlist
- All components were built with control of Ethos and checked to fit datasheets and part numbers

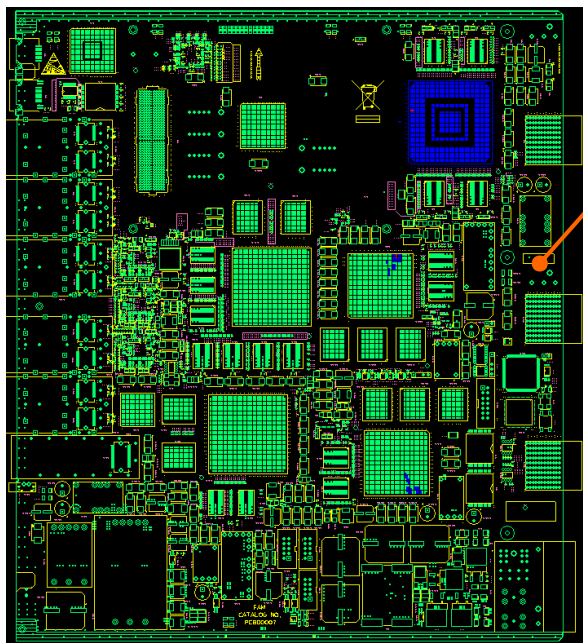


* Layout pics courtesy of Oranit-PCB LLD

Layout Flow with Allegro

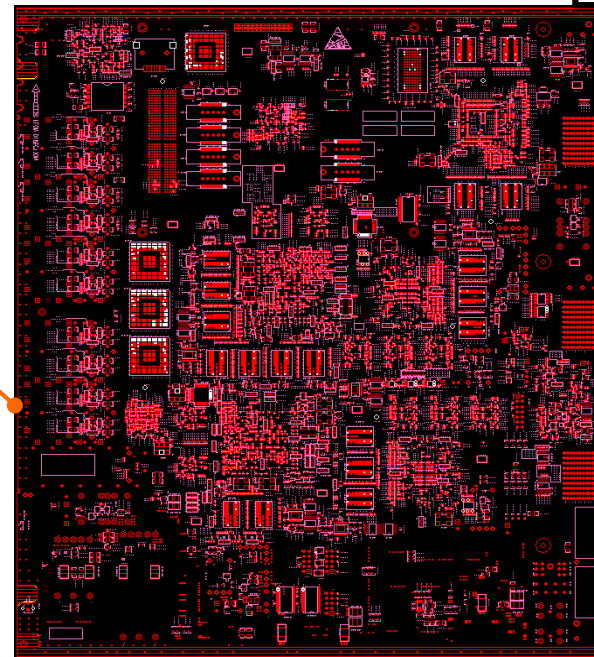
Card Placement:

- *DXF should be ready prior to placement*
- *Placement according to thermal simulations*
- *Final placement to be confirmed by thermal, mechanical & technological engineers*

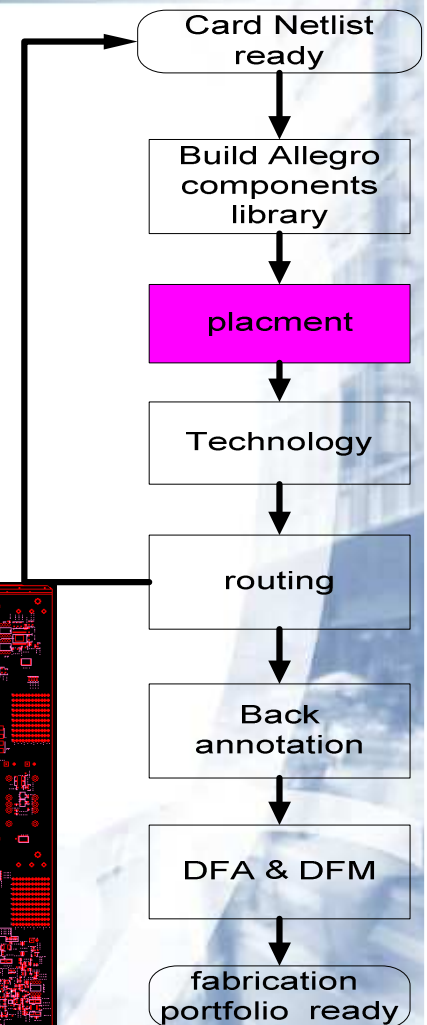


ELIC20 CS

ELIC20 PS



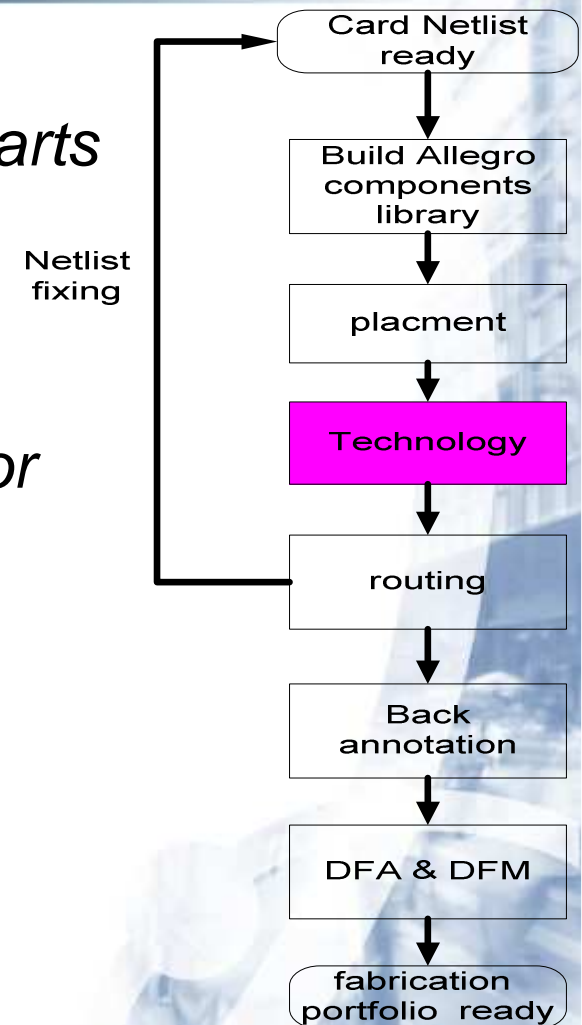
Netlist
fixing



Layout Flow with Allegro

Technology:

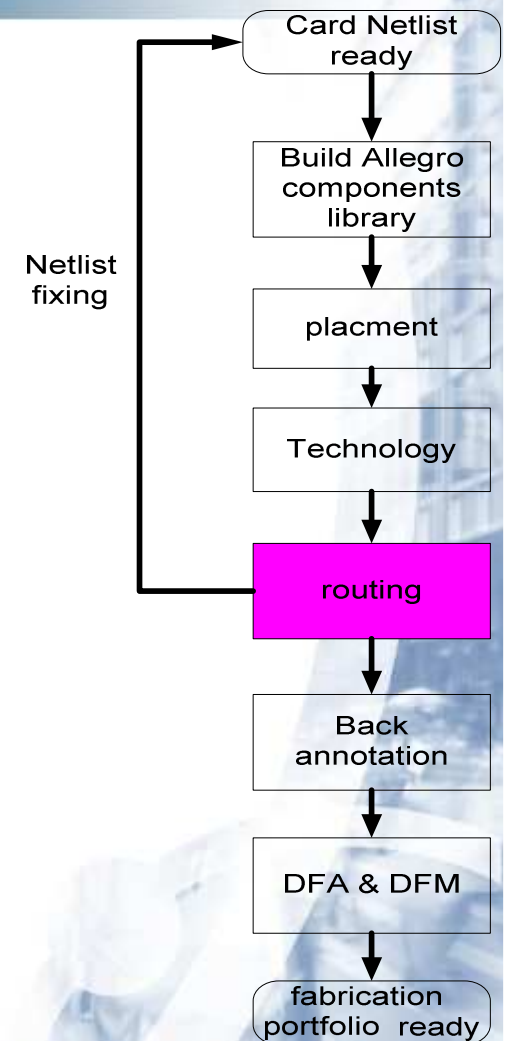
- *Stack-up should be ready before routing starts (including power planes and EMC issues)*
- *All library components checked by technologist to confirm pad size, etc...*
- *Simulation of microstrip, or stripline done for single ended and differential pairs of each layer.*
- *All technology aspects confirmed by PCB manufacturer and card assembly factory*



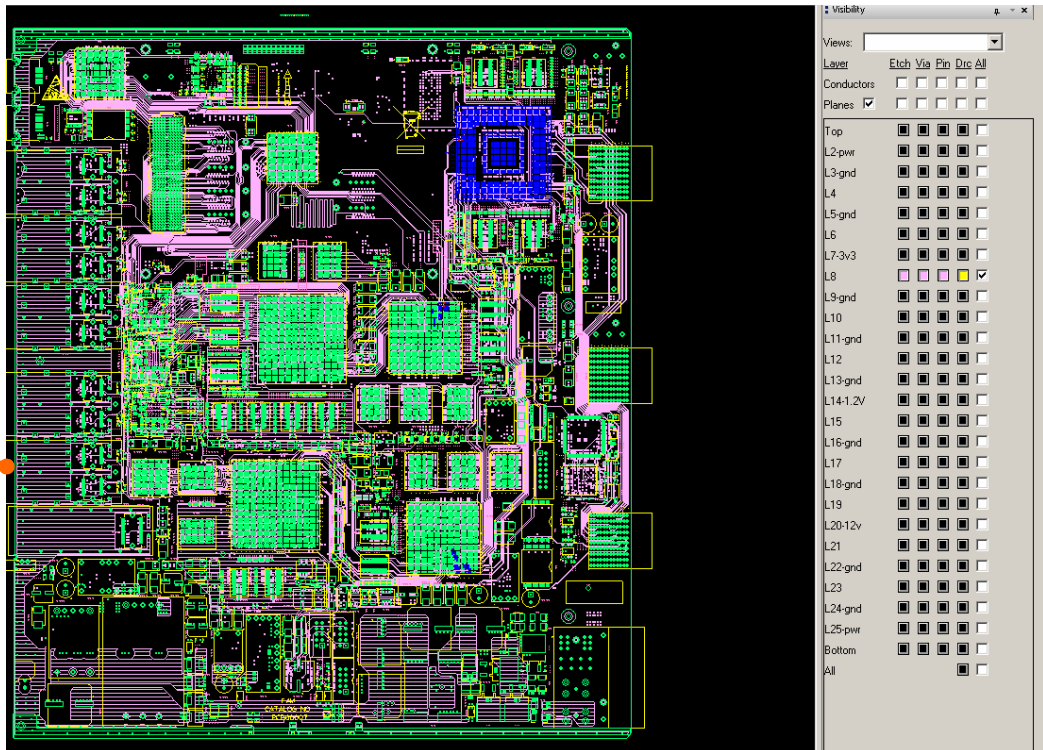
Layout Flow with Allegro

Routing:

- 25,000 nets routed manually ~ 3 months
- Routing starts at fan-out of all components at placement phase
- Routing takes into account netlist bugs



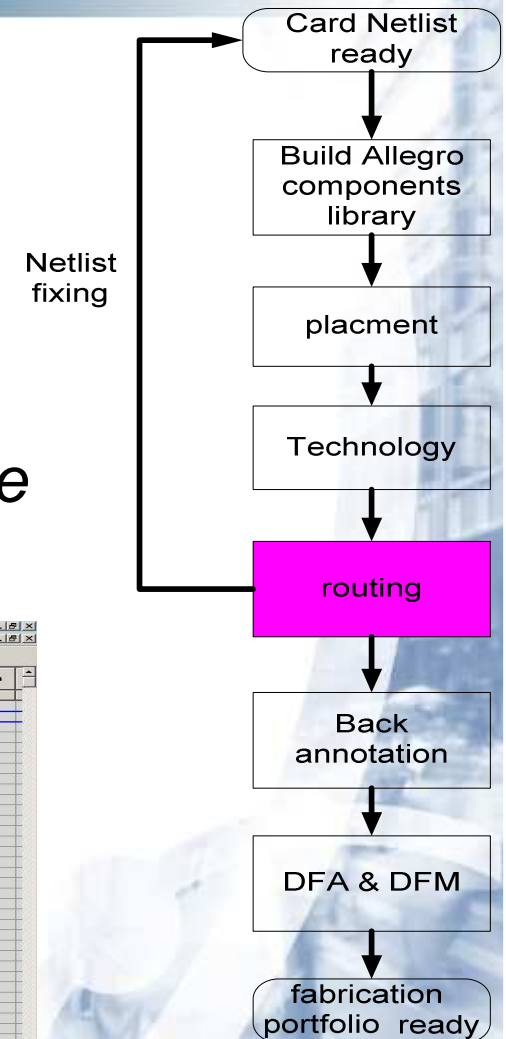
Allegro 15.5.1



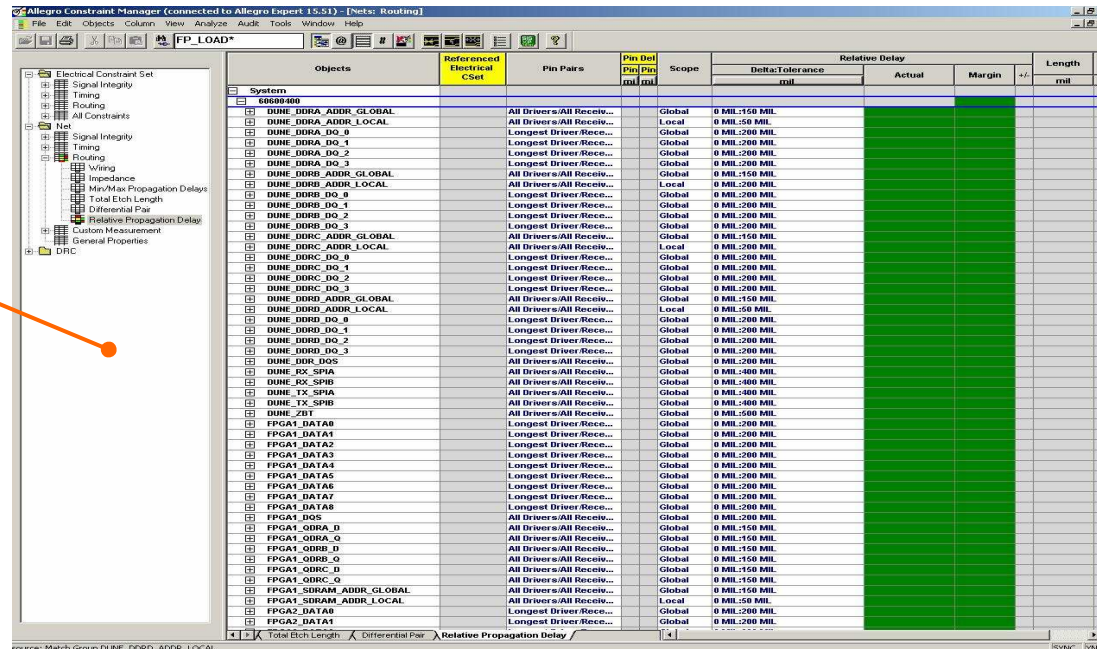
Layout Flow with Allegro

Routing & Constrains:

- Around ~1,000 constrains made at schemes drawing phase
- Constrains help to control & find bugs at routing phase
- Fixing routing according to constrains can take around 3 weeks



Constraint manager

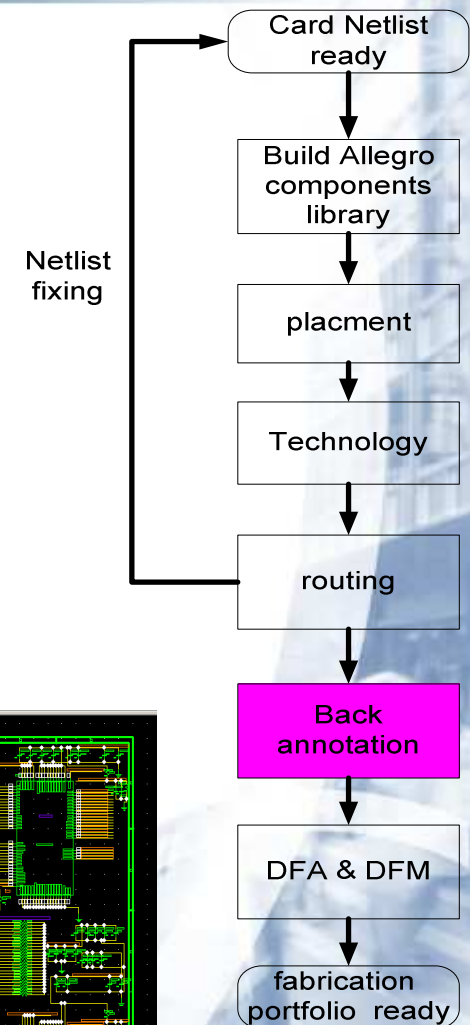
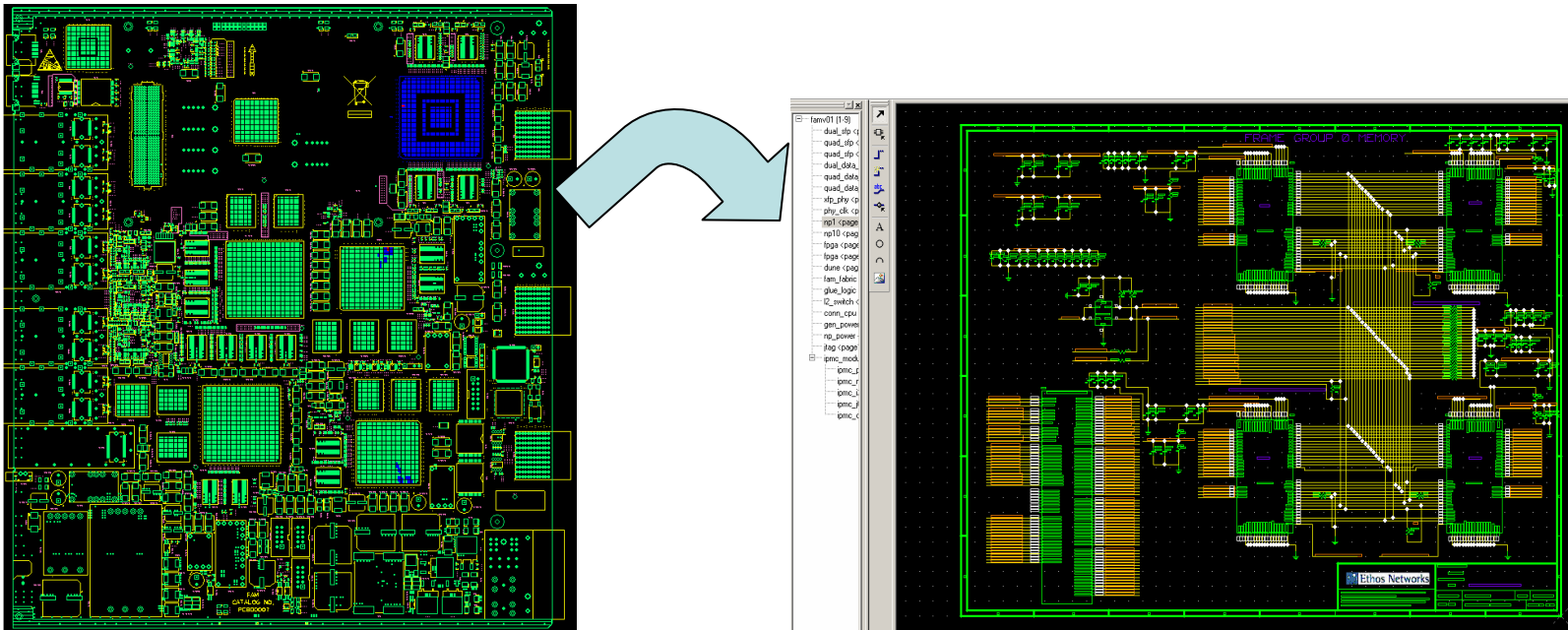


Objects	Referenced Electrical Cset	Pin Pairs	Pin Del	Pin Pin	Scope	Delta Tolerance mil	Actual	Margin	Length mil
60000400									
DUNE_D0RA_ADDR_GLOBAL		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
DUNE_D0RA_ADDR_LOCAL		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
DUNE_D0RA_D0_0		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RA_D0_1		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RA_D0_2		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RA_D0_3		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RB_ADDR_GLOBAL		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
DUNE_D0RB_ADDR_LOCAL		All Drivers/All Receiv...			Local	0 MIL:200 MIL			
DUNE_D0RB_D0_0		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RB_D0_1		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RB_D0_2		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RB_D0_3		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RC_ADDR_GLOBAL		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
DUNE_D0RC_ADDR_LOCAL		All Drivers/All Receiv...			Local	0 MIL:200 MIL			
DUNE_D0RC_D0_0		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RC_D0_1		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RC_D0_2		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RC_D0_3		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RD_ADDR_GLOBAL		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
DUNE_D0RD_ADDR_LOCAL		All Drivers/All Receiv...			Local	0 MIL:150 MIL			
DUNE_D0RD_D0_0		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RD_D0_1		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RD_D0_2		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RD_D0_3		Longest Driver Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RX_SPIA		All Drivers/All Receiv...			Global	0 MIL:200 MIL			
DUNE_D0RX_SPIB		All Drivers/All Receiv...			Global	0 MIL:400 MIL			
DUNE_TX_SPIA		All Drivers/All Receiv...			Global	0 MIL:400 MIL			
DUNE_TX_SPIB		All Drivers/All Receiv...			Global	0 MIL:400 MIL			
DUNE_D0T		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
FGCA1_DATA0		Longest Driver Receiv...			Global	0 MIL:200 MIL			
FGCA1_DATA1		Longest Driver Receiv...			Global	0 MIL:200 MIL			
FGCA1_DATA2		Longest Driver Receiv...			Global	0 MIL:200 MIL			
FGCA1_DATA3		Longest Driver Receiv...			Global	0 MIL:200 MIL			
FGCA1_DATA4		Longest Driver Receiv...			Global	0 MIL:200 MIL			
FGCA1_DATA5		Longest Driver Receiv...			Global	0 MIL:200 MIL			
FGCA1_DATA6		Longest Driver Receiv...			Global	0 MIL:200 MIL			
FGCA1_DATA7		Longest Driver Receiv...			Global	0 MIL:200 MIL			
FGCA1_DATA8		Longest Driver Receiv...			Global	0 MIL:200 MIL			
FGCA1_D0S		All Drivers/All Receiv...			Global	0 MIL:200 MIL			
FGCA1_D0RA_D		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
FGCA1_D0RA_Q		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
FGCA1_D0RB_D		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
FGCA1_D0RB_Q		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
FGCA1_D0RC_D		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
FGCA1_D0RC_Q		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
FGCA1_SDRAM_ADDR_GLOBAL		All Drivers/All Receiv...			Global	0 MIL:150 MIL			
FGCA1_SDRAM_ADDR_LOCAL		All Drivers/All Receiv...			Local	0 MIL:150 MIL			
FGCA2_DATA0		Longest Driver Receiv...			Global	0 MIL:200 MIL			
FGCA2_DATA1		Longest Driver Receiv...			Global	0 MIL:200 MIL			

Layout Flow with Allegro

Back Annotation & Silk:

- *Silk & refdes should be back annotated to design Concept HDL*
- *Small areas of layout can be back annotated*
- *All 0402 components were removed from silk (hard to debug)*



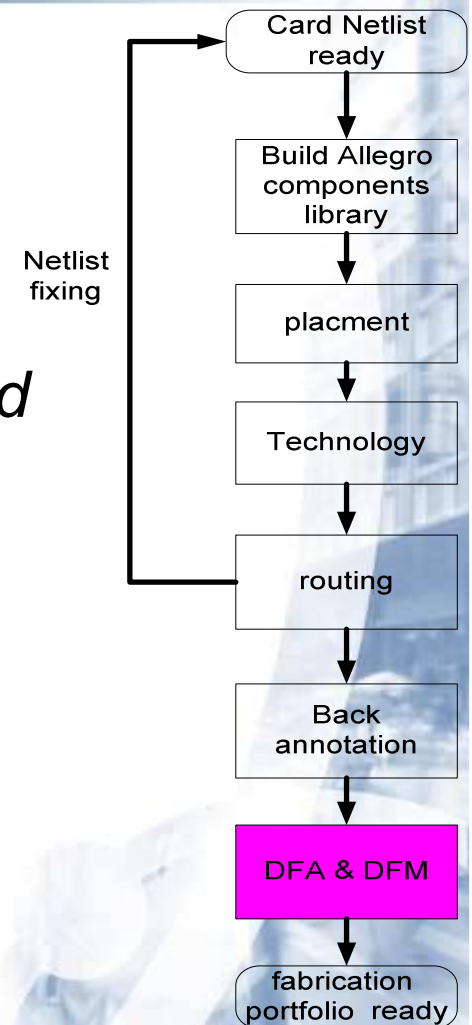
Layout Flow with Allegro

DFM (Design For Manufacturing):

- *All cards routing passed Valor manufacturing tests (net-to-via proximity, etc...)*
- *Around 12,000 errors where discovered & fixed*

DFA (Design For Assembly):

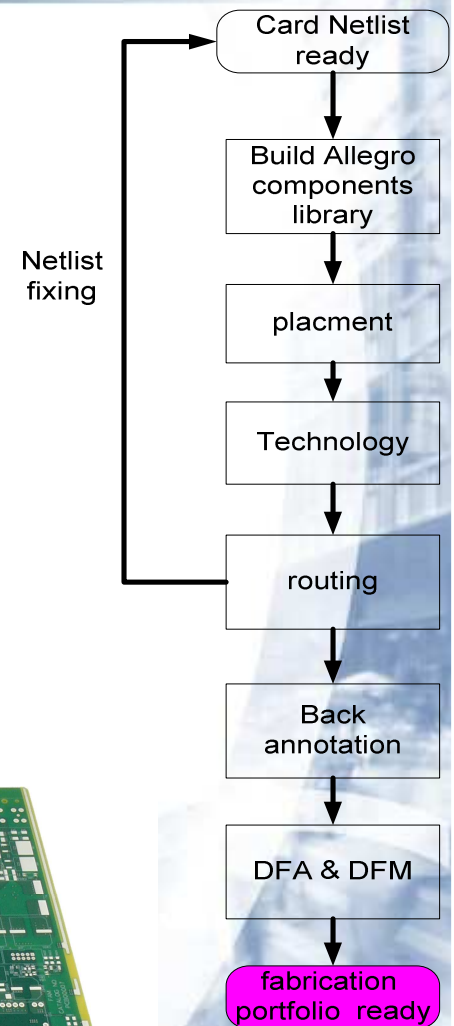
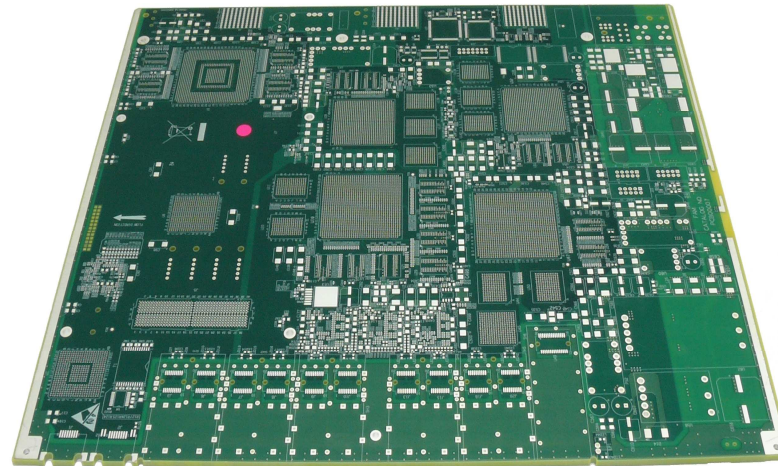
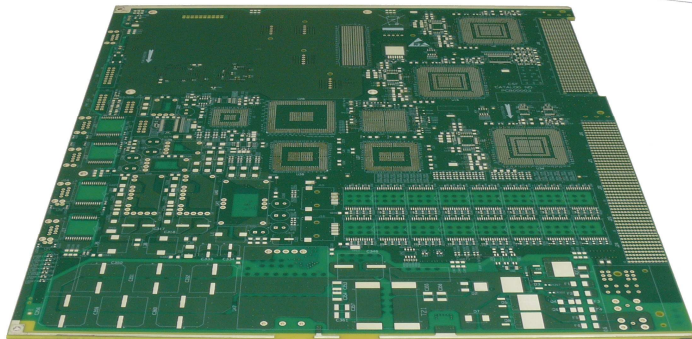
- *All cards passed Valor assembly checking for placement problems*
- *BGA keeps 2.5mm from all sides for possible conflicts at work around*



Layout Flow with Allegro

Fabrication Portfolio Ready:

- *All DFA, DFM, Thermal, Mechanics, Technology aspects tested and checked*
- *Gerbers, ODB databases sent to PCB and assembly manufactures*
- *Standard PCB (through VIA's) delivered within 5 working days*
- *Laser 1-2 , 1-3 PCB (HDI technology) delivered within 10-12 working days*



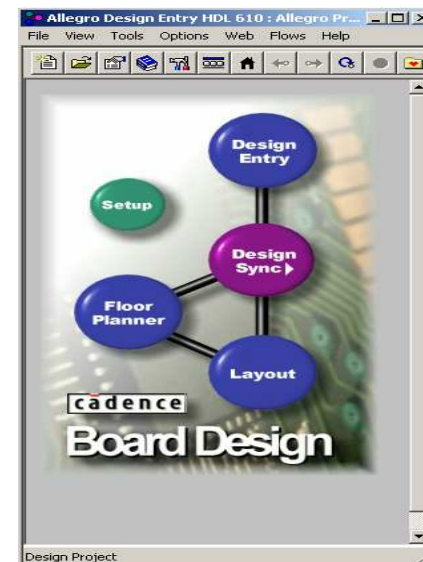
Allegro Summary

Advantages:

- *Team sharing and integration (at peak time up to 8 layout designers worked together)*

Possible Improvements:

- *At final stages of layout ,large files were hard to manage*
- *Back annotation to Concept need to have better support of instantiations blocks*



VoD

IPTV

Mobile Backhauling

One network

Hundreds of SLAs

Ethos FPGA Design with Incisive Enterprise



FPGA Design with Incisive Enterprise

DynTETM (Dynamic Traffic Engineering) FPGA :

- 10Gbps full duplex SPI4.2 based interfaces*
- 5 x DDRII @ 667Mbps interfaces*
- 3 x QDRII @ 250MHz*
- 800 functional I/O's*
- Equivalent of 4Mgates of ASIC*
- All components written in Ethos and Ethos-IP*
- Verification under Linux RH enterprise 4.0 x64bit version*
- Incisive Enterprise 5.8 edition*

FPGA Design with Incisive Enterprise

Block Functional Specification :

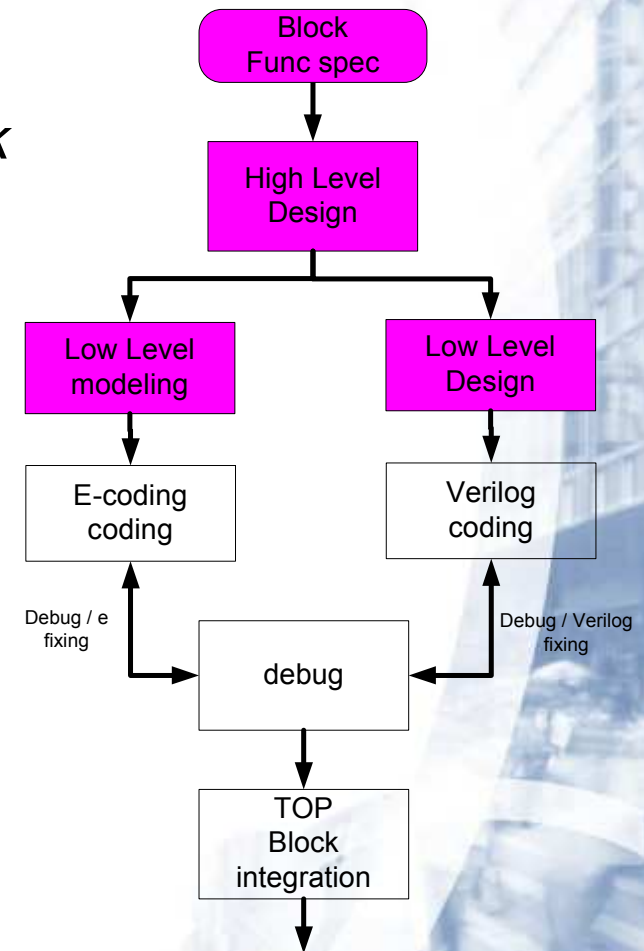
- Functional specs were written for each block
- All blocks are part of TOP functional spec

HLD (High Level Design) Documents :

- HLD is written for each block
- From HLD each team writes the LLD

LLD (Low Level Design) Documents:

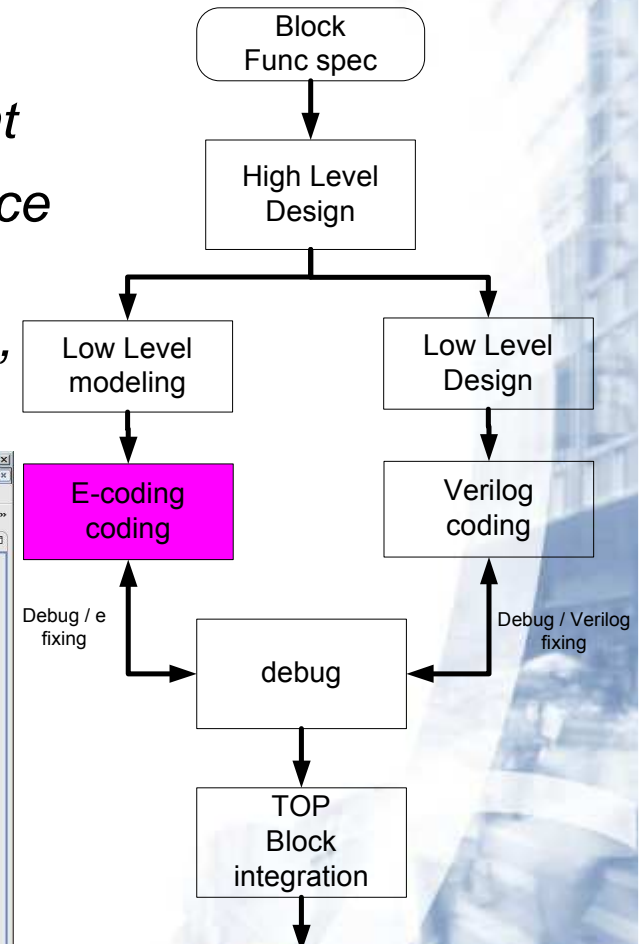
- LLD is detailed down to logical gates before code writing starts
- E-coding referring to block HLD only



FPGA Design with Incisive Enterprise

E-coding:

- *E-code coded at Eclipse Open-source environment*
- *E-code is version controlled within SVN open source tool*
- *eRM methodology reduces coding time (interfaces, chip level reuse)*



Eclipse environment
Support e-language
color coding



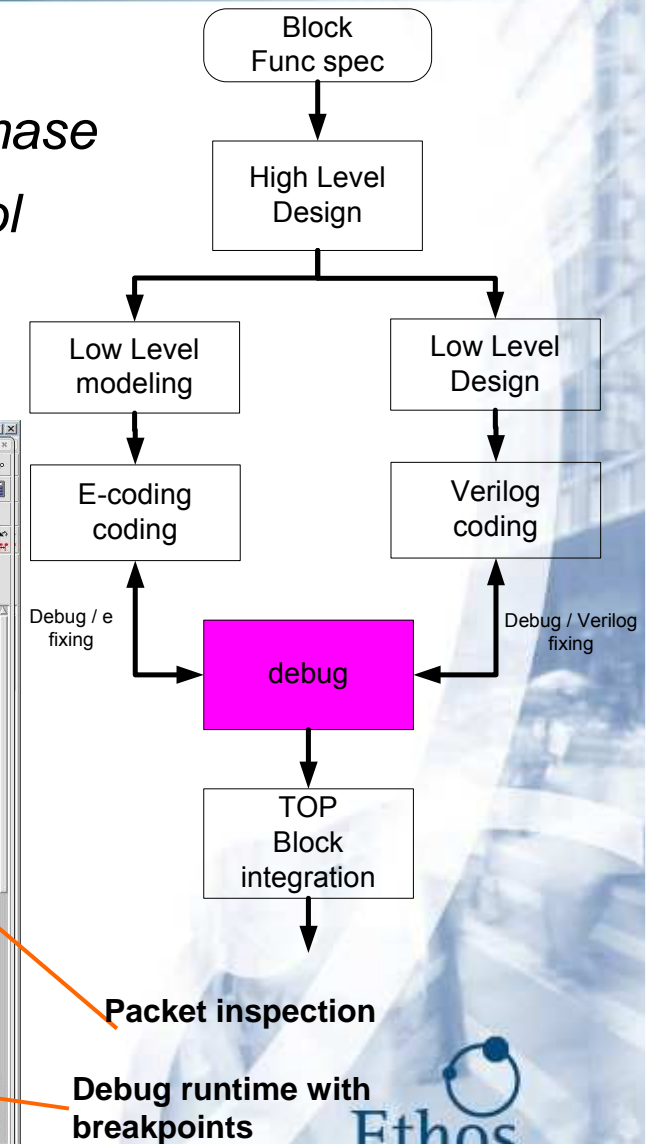
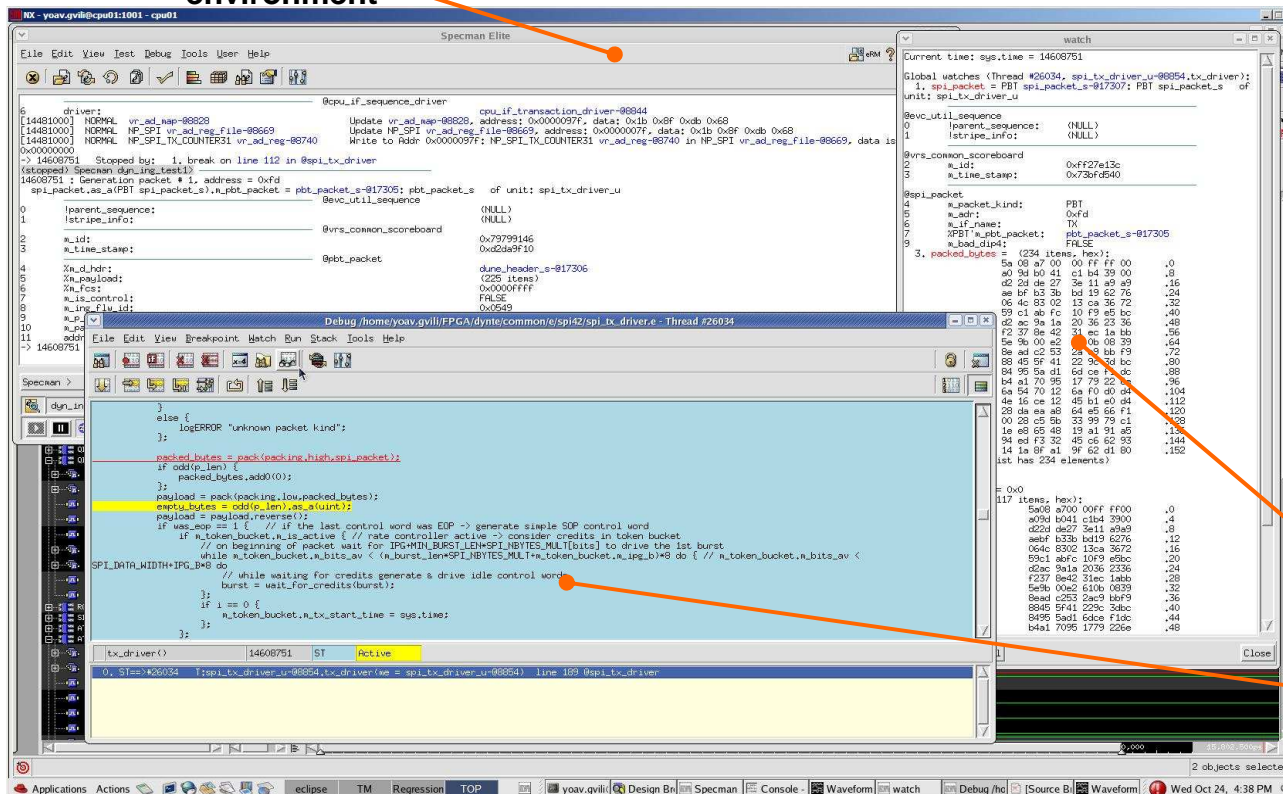
A screenshot of the Eclipse IDE interface. The main editor window displays Verilog code with syntax highlighting. The code includes module declarations, signal definitions, and logic blocks. The interface shows various Eclipse toolbars and a project explorer on the left. The status bar at the bottom indicates the current file and project.

FPGA Design with Incisive Enterprise

Debug:

- E-code and V-code are prepared prior to debug phase
- Bugs are documented in Bugzilla Open-source tool
- Debug of each block includes coverage function

Specman environment



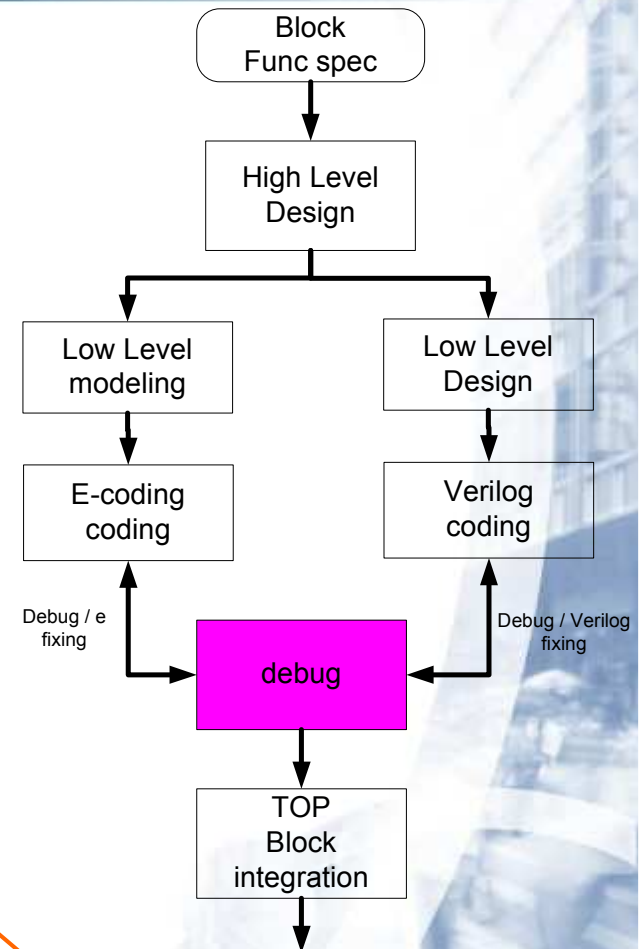
Packet inspection

Debug runtime with breakpoints

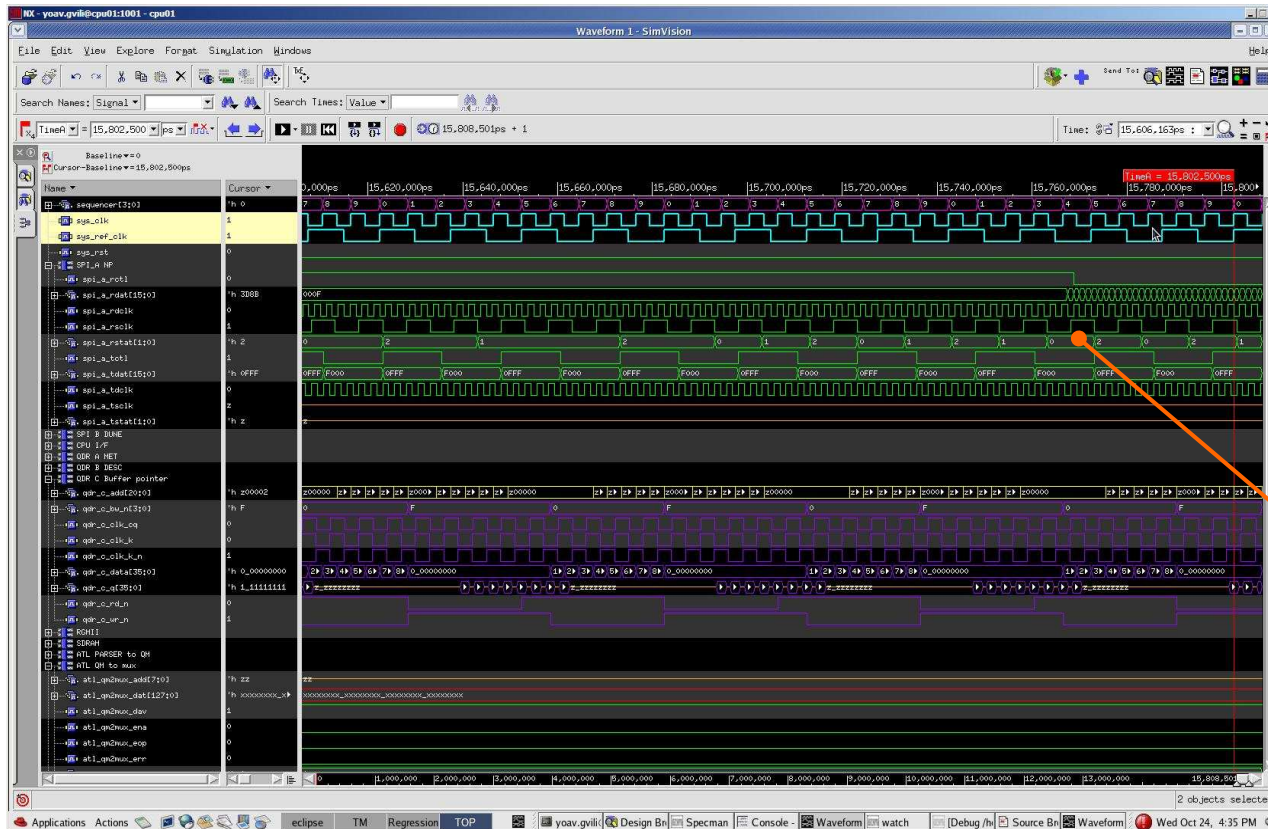
FPGA Design with Incisive Enterprise

Debug:

- *Integrated environment of ncVerilog & Specman helps reduce simulations cycles*
- *Full chip logical simulation run for 8 hours*



SimVision
environment wave
forms



FPGA Design with Incisive Enterprise

Advantages:

- *Bugs found by verification reduce the lab debug cycle*
- *eRM writing methodology reduce coding time*
- *VR_AD of CPU (great model !!) reduced time and coding of CPU interface (register and memory model package)*
- *IE enable excellent team work methodology*

Possible Improvements:

- *Integration of IE tools will reduce time at simulation stage*
- *Support of IC (DDR, QDR etc..) models to improve simulation time*



Thank You

Ethos - es [NL, fr. GK *ēthos*]
character, sentiment, the
guiding beliefs, standards, the
spirit that motivates the ideas